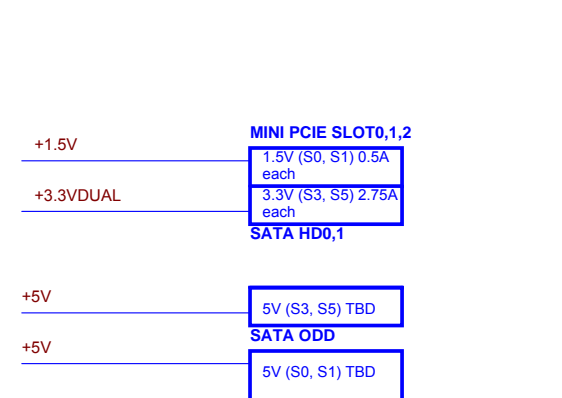
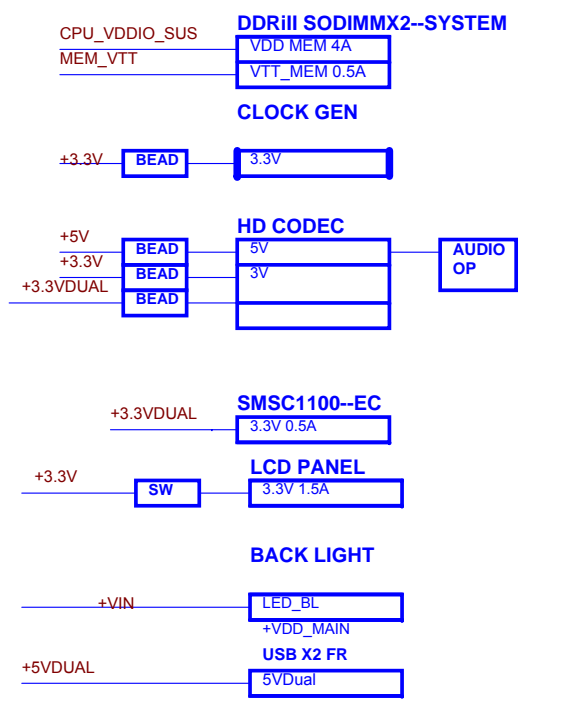
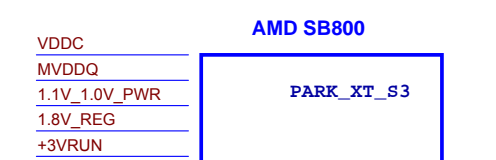
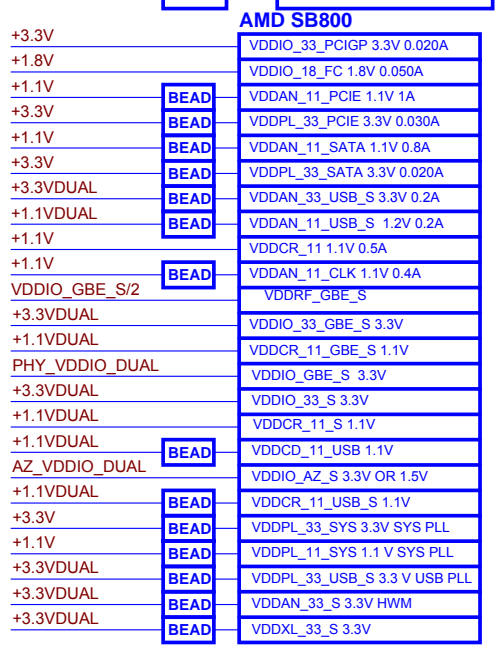
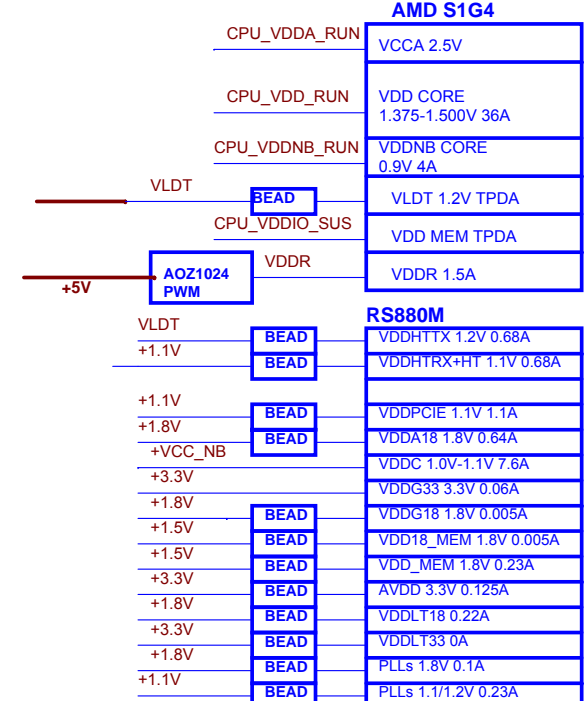
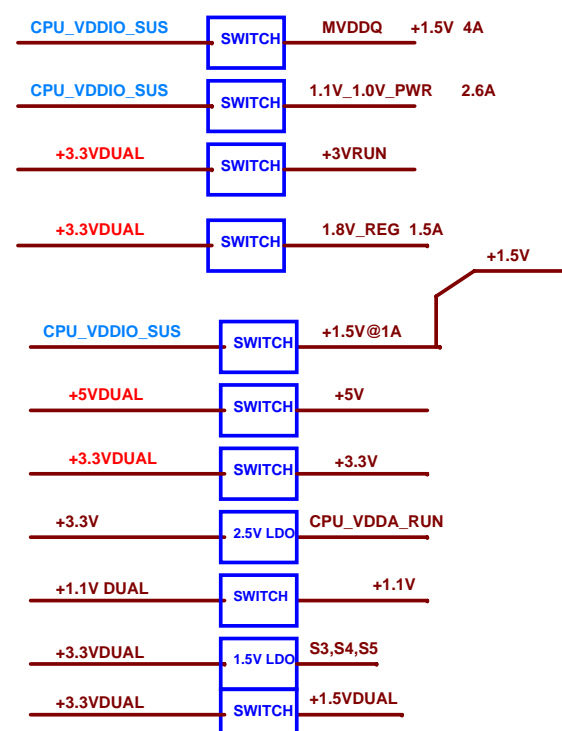
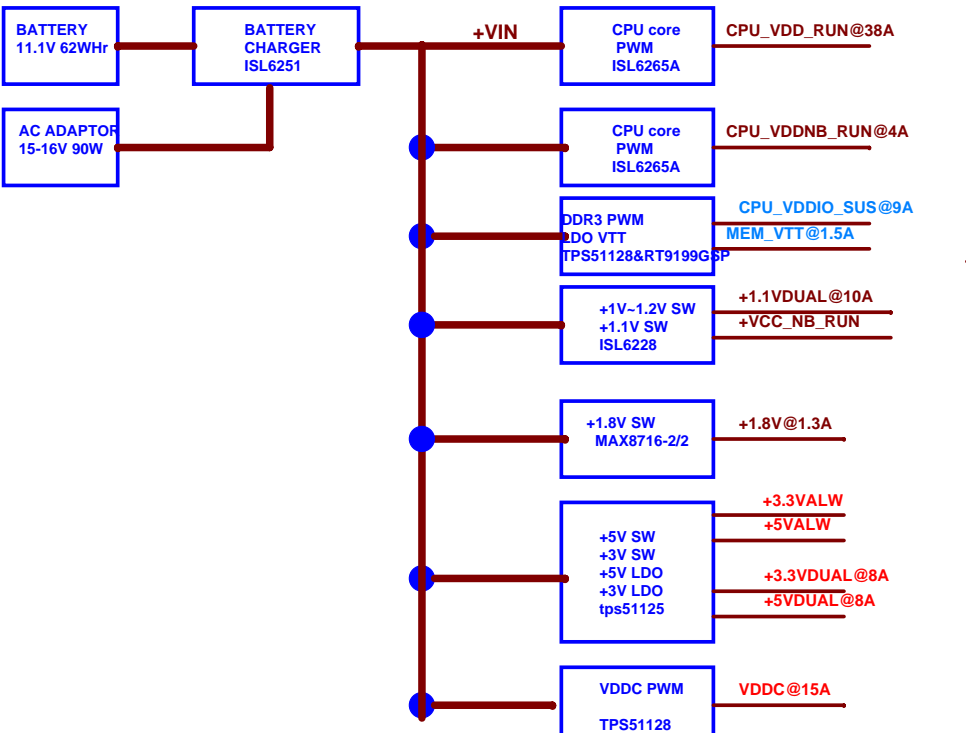
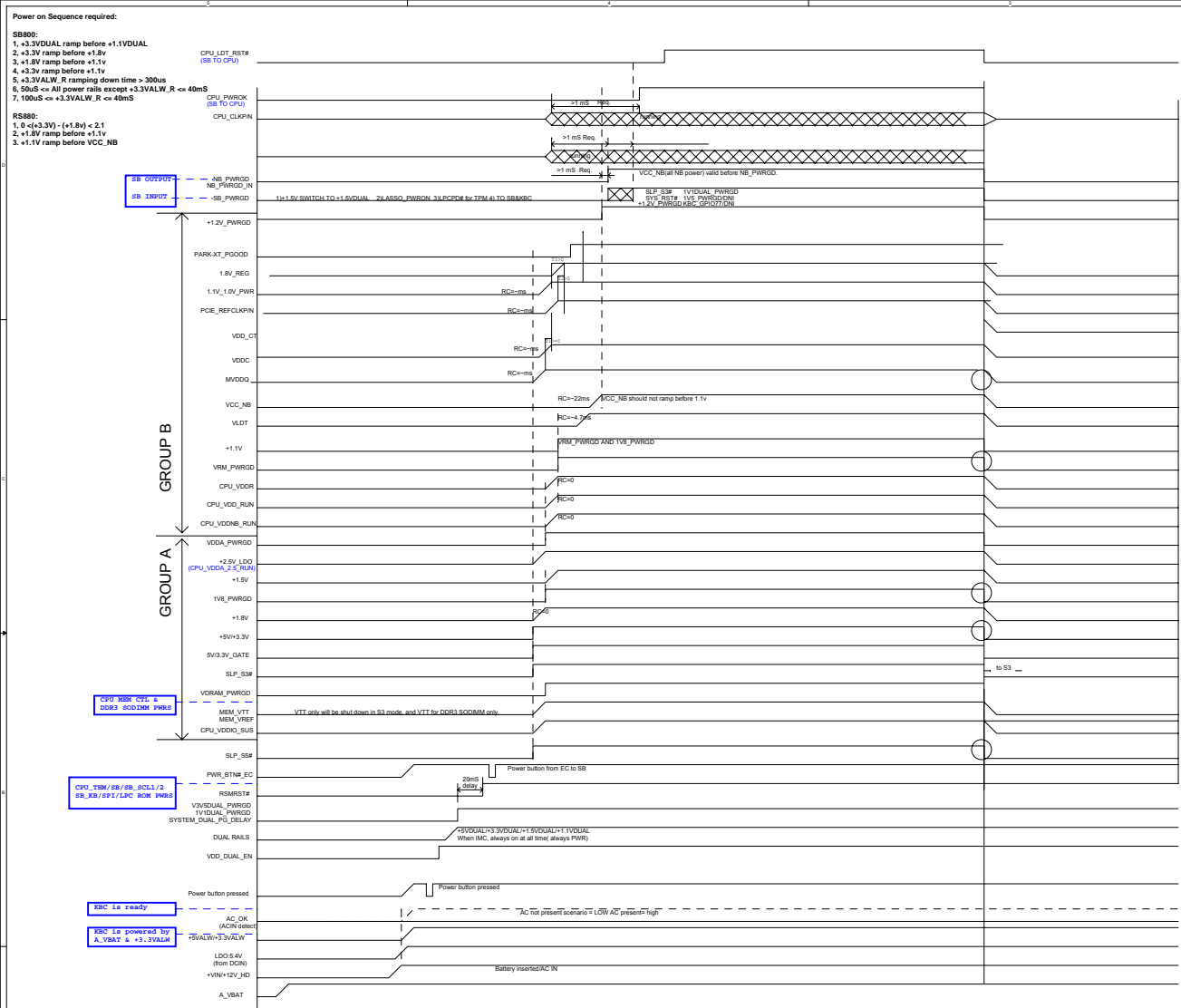


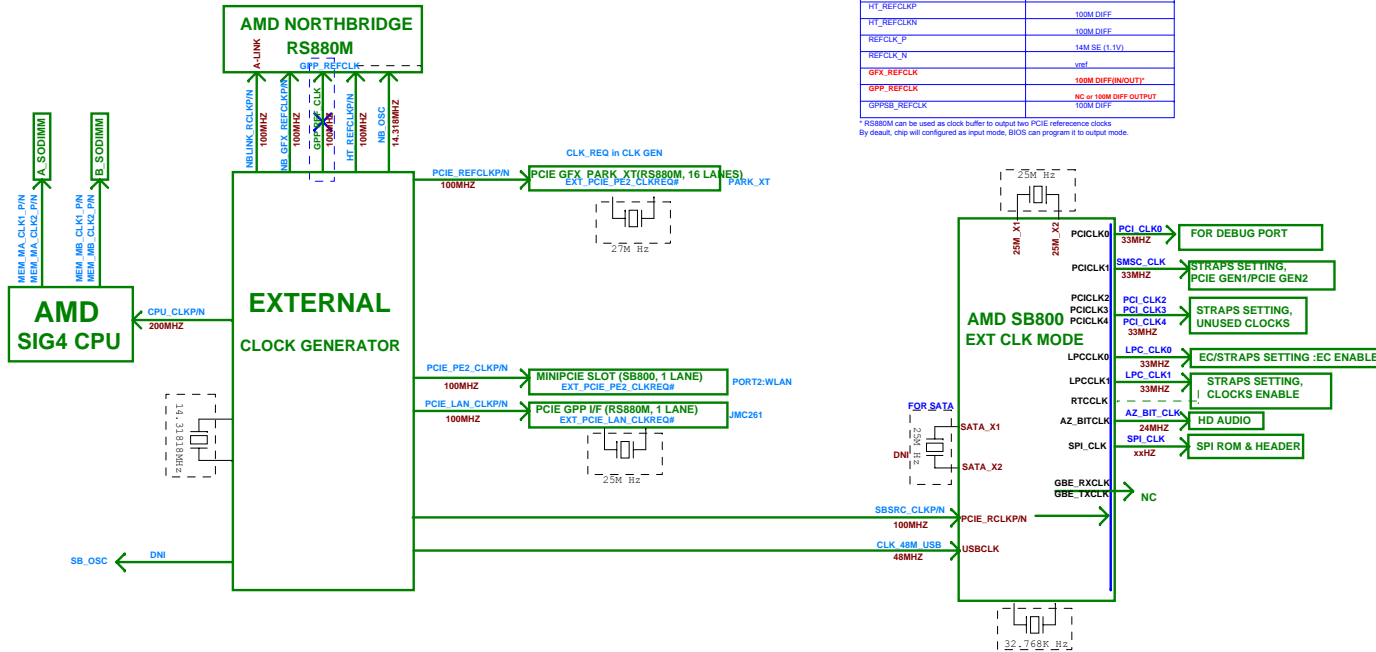
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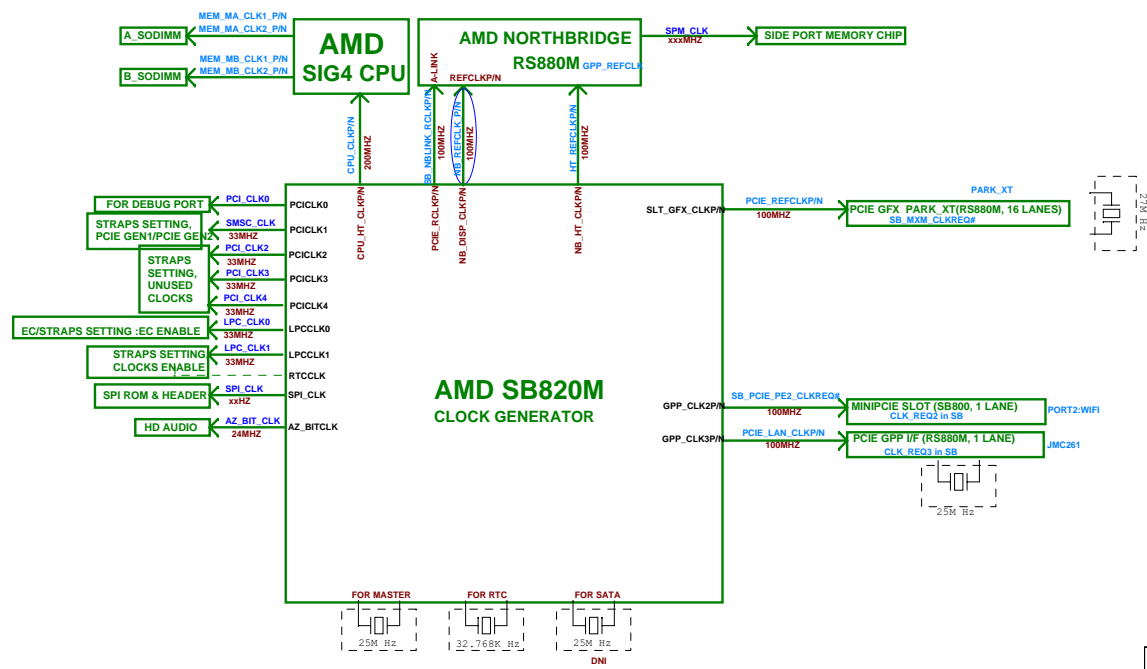




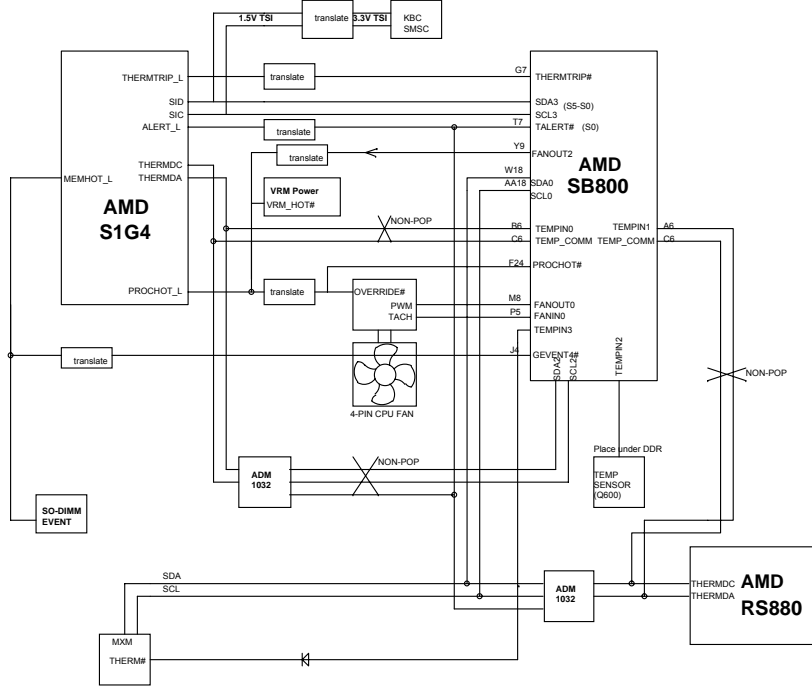
EXTERNAL CLOCK MODE



INTERNAL CLOCK MODE



Thermal Systems (Emergency Shutdown, Throttling, Fan Control)

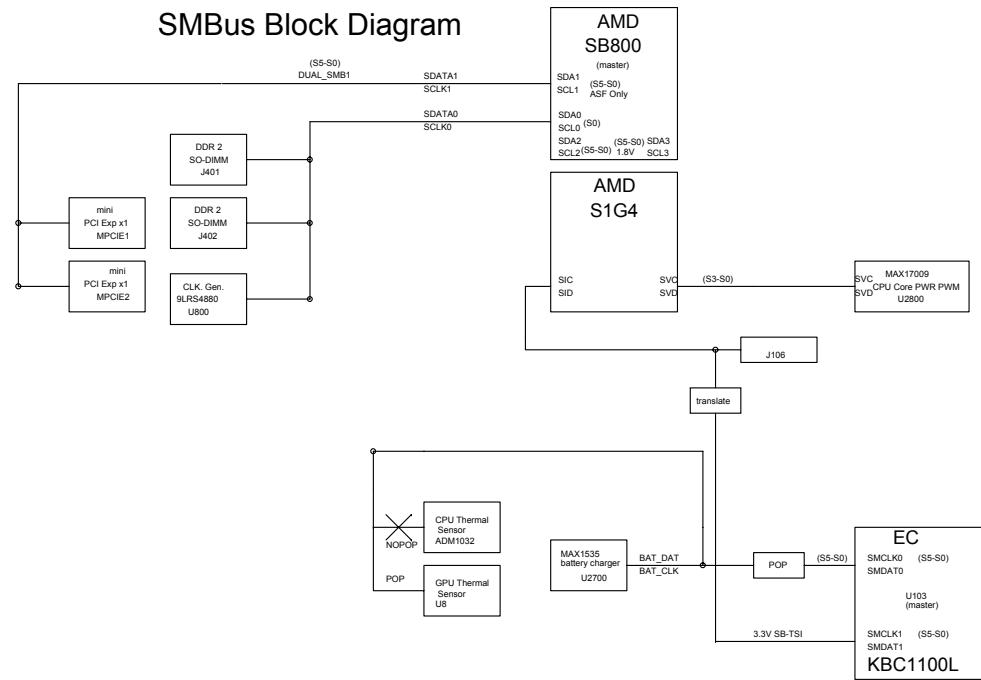


Thermal disaster prevention is implemented by PROCHOT_L and THERMTRIP_L with hardware non-system dependant functions. Fan speed control will only be implemented by SB TSI software based implementation

Power State / Voltage Rail Activity Summary

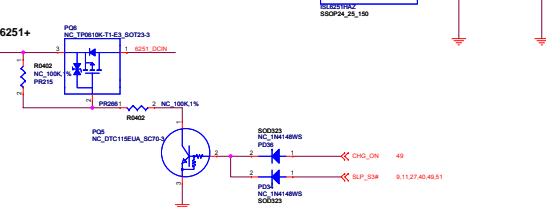
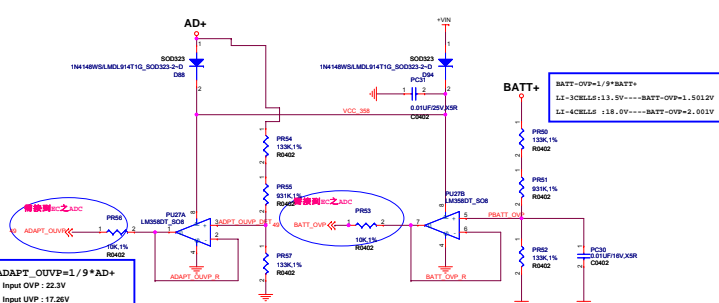
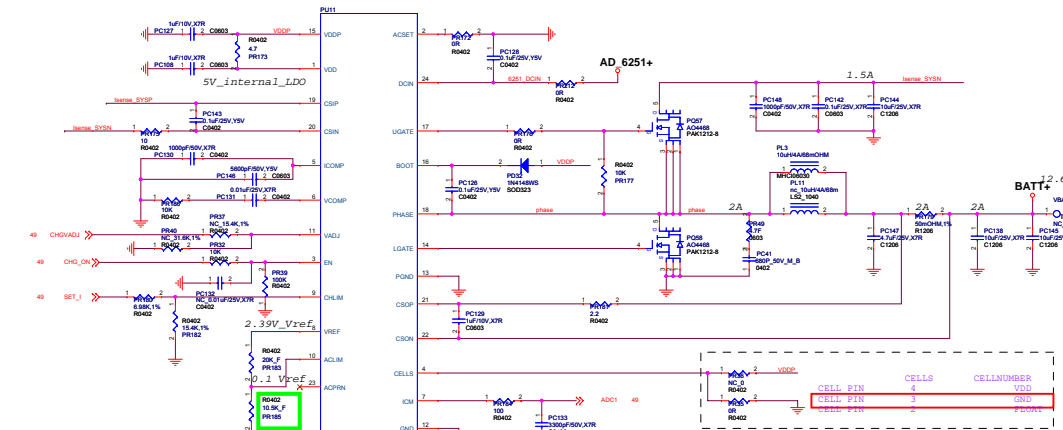
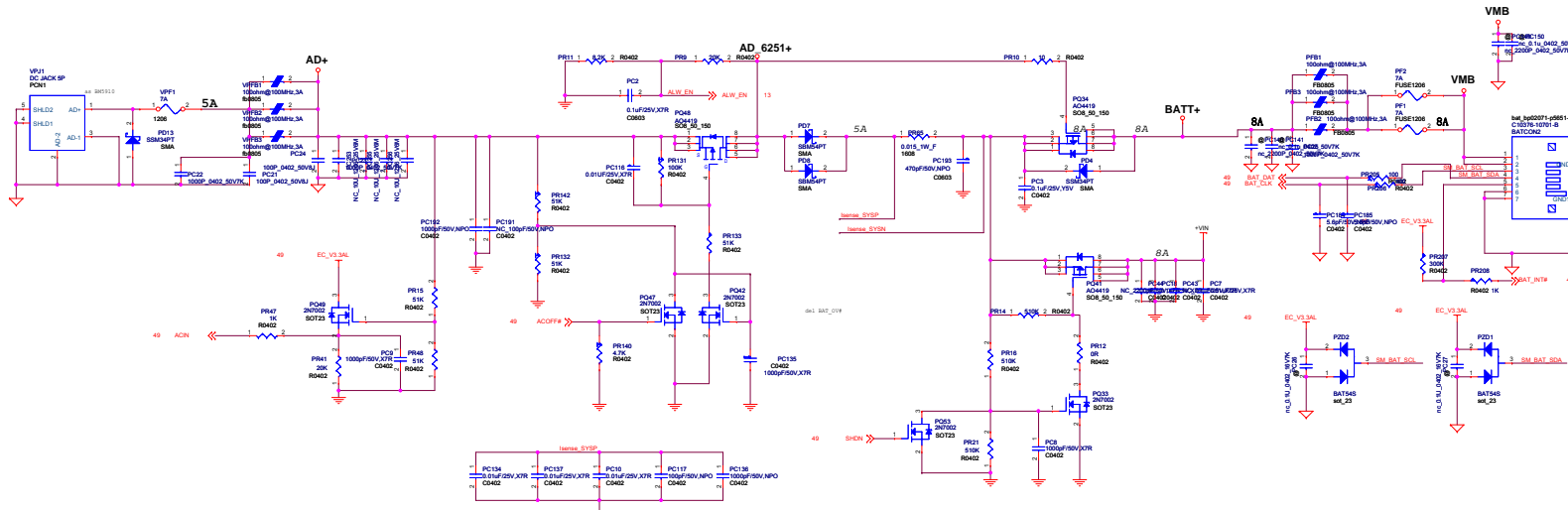
Global System State	Sleep State	Processor Power State	Description	RTC	ALW	DUAL	SUS	RUN
G0	S0	C0	Running	ON	ON	ON	ON	ON
G0	S0	C0	Running	ON	ON	ON	ON	ON
G0	S0	C1	P-state transitions under OS control	ON	ON	ON	ON	ON
G0	S0	C2	Halt	ON	ON	ON	ON	ON
G0	S0	C2	Stop grant, caches snooperable	ON	ON	ON	ON	ON
G0	S0	C3	TBD	ON	ON	ON	ON	ON
G0	S0	C4	TBD	ON	ON	ON	ON	ON
G1	S1	OFF	Powered on suspend	ON	ON	ON	ON	ON
G1	S3	OFF	Sleeping	ON	ON	ON	ON	OFF
G2	S4	OFF	Suspend to RAM	ON	ON	ON	OFF	OFF
G2	S5	OFF	Suspend to disk	ON	ON	ON	OFF	OFF
G2	S5	OFF	Soft-off	ON	ON	ON	OFF	OFF
G2/G3	S5 LOW	OFF	Battery IN	ON	ON	OFF	OFF	OFF
G3	OFF	OFF	Mechanical off	ON	OFF	OFF	OFF	OFF

SMBus Block Diagram



Group Name Description

INT: Stuff when use internal clock generator
 EXT: Stuff when use external clock generator
 DNI/NC: DO NOT INSTALL
 KBC: Stuff when use external KBC
 IMC: Stuff when use internal EC
 A11: Resistors marked with "A11" is only for SB800A11 ONLY.



Layout note:
Far away from critical signal trace

设置适配器限流值为
100mV/25m Ohm=4.0A.

$I_{aclim} = 1/PR8 * (0.05 * V_{aclim} / V_{ref} + 0.05)$

SET_I 充电电流

0V	0A
0.66V	400mA
3.3V	2A

$I_{CHG} = 165mV / PR179 * (V_{CHLM} / 3.3V)$

CELL PIN	CELLS	CELLNUMBER
1	4	VDD
2	4	VDD
3	4	VDD
4	4	VDD

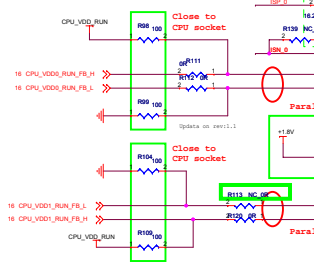
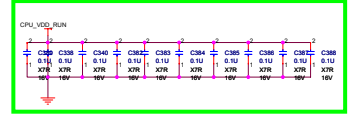
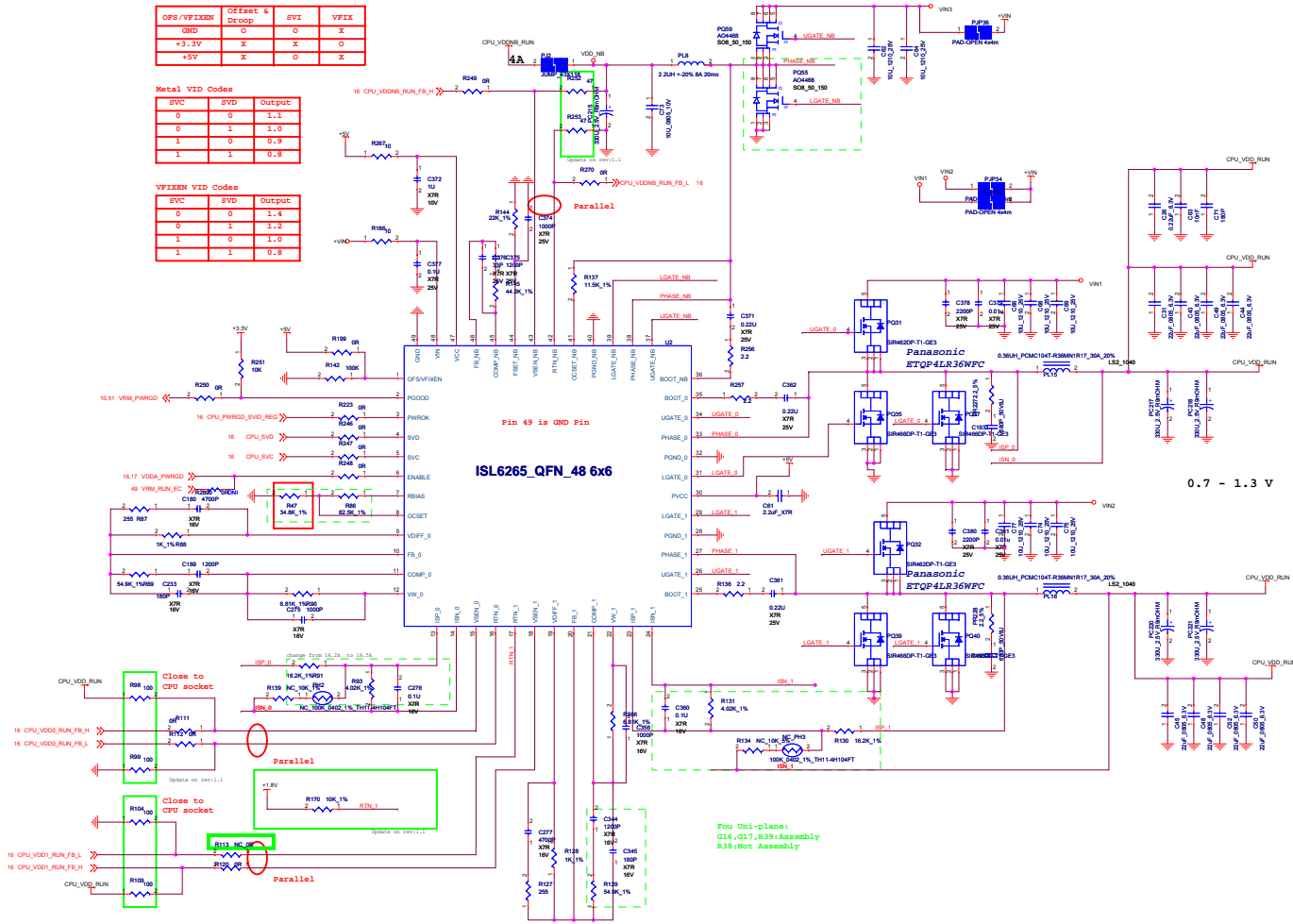
QFS/VFIXN	Offset & Droop	SVC	VFIX
GND	0	0	X
+3.3V	X	X	0
+5V	X	0	X

Metal VID Codes

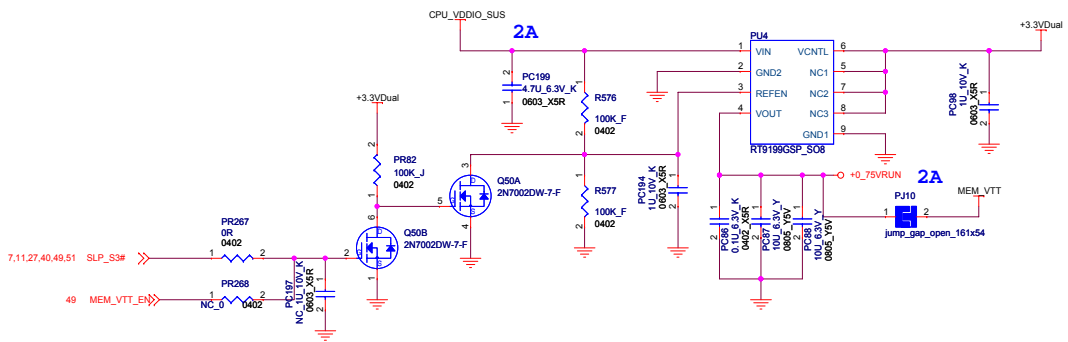
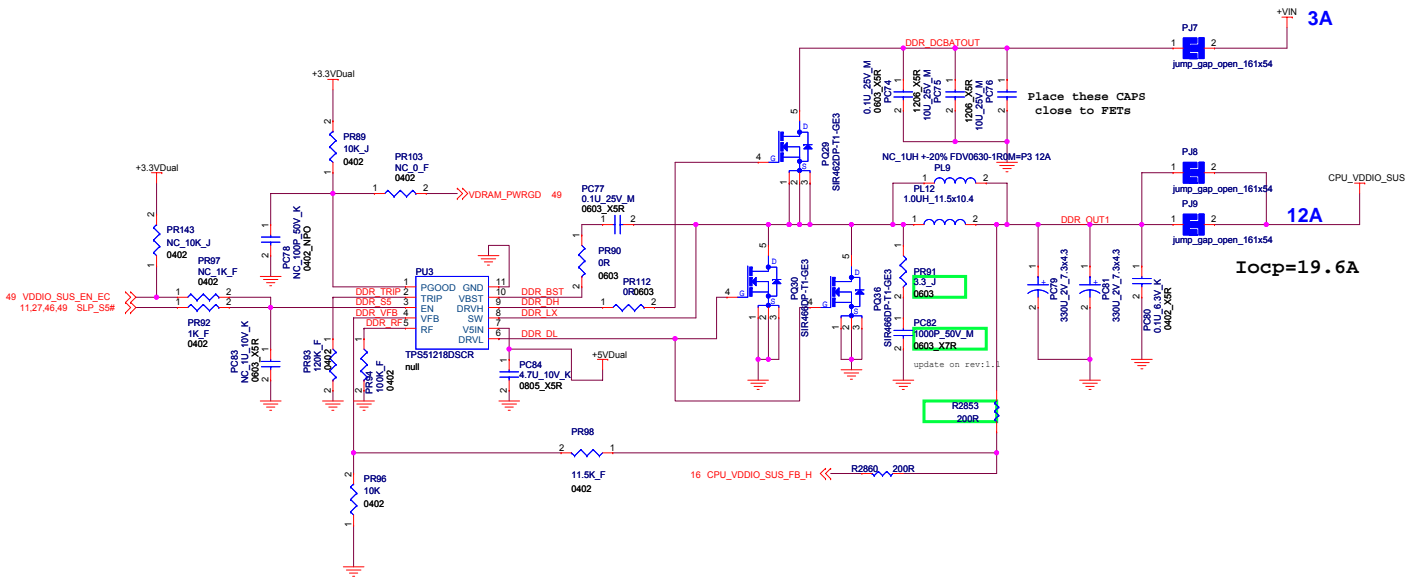
SVC	SVD	Output
0	0	1.1
0	1	1.0
1	0	0.9
1	1	0.8

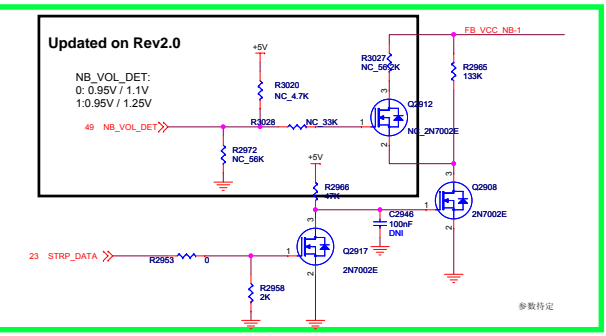
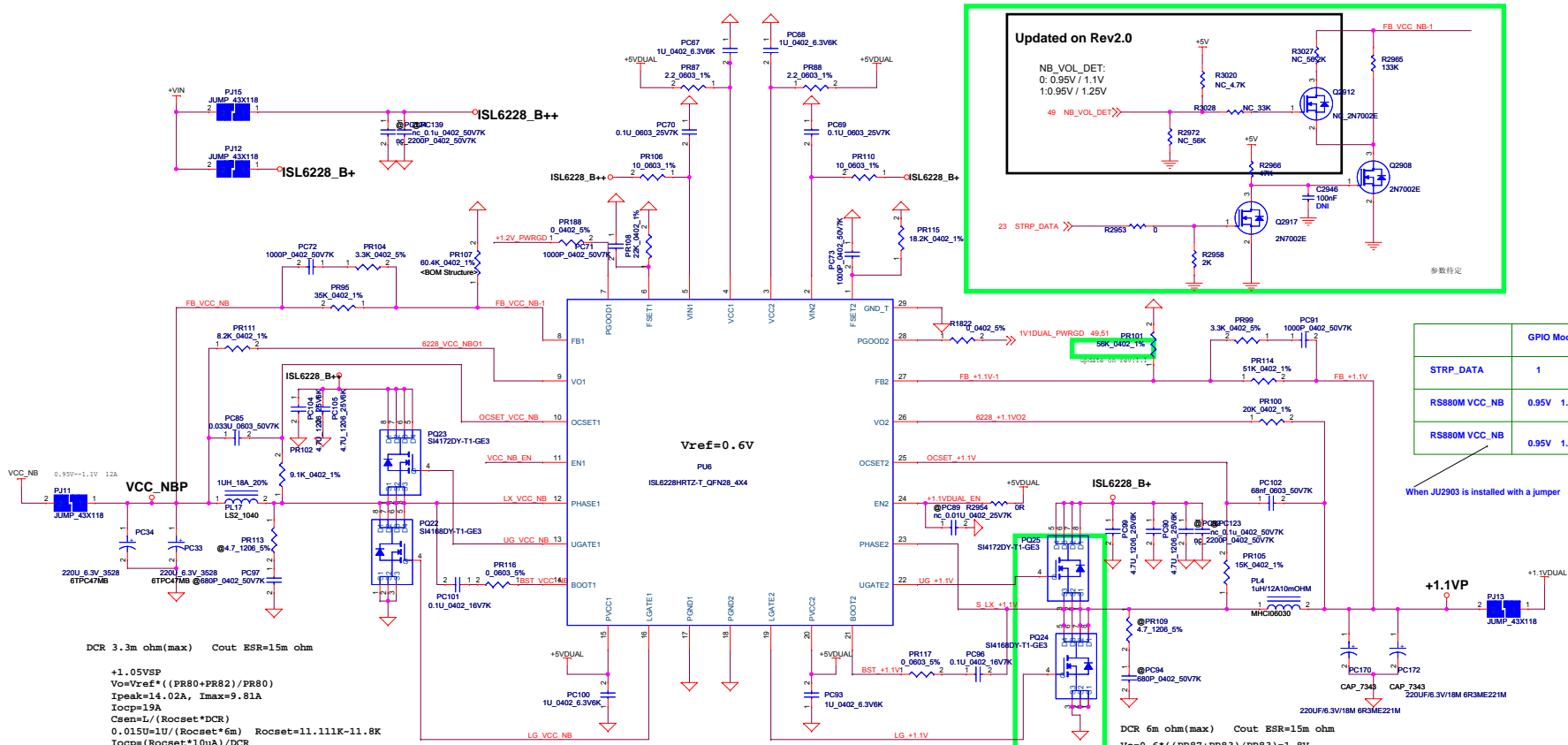
VFIXEN VID Codes

SVC	SVD	Output
0	1	1.4
0	0	1.3
1	0	1.0
1	1	0.8



For Uni-planes:
G16,G17,R39:Assembly
R38:Not Assembly



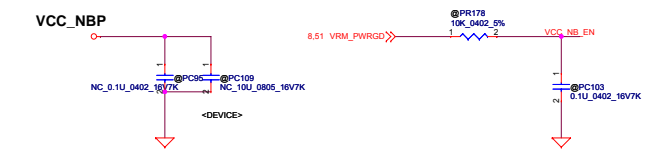


	GPIO Mode	Power Shift
STRP_DATA	1 0	PWM
RS880M VCC_NB	0.95V 1.1V	N/A
RS880M VCC_NB	0.95V 1.25V	

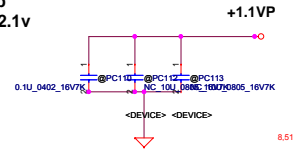
When JU2903 is installed with a jumper

DCR 3.3m ohm(max) Cout ESR=15m ohm

+1.05VSP
 $V_o = V_{ref} * ((PR80 + PR82) / PR80)$
 $I_{peak} = 14.02A, I_{max} = 9.81A$
 $I_{ocp} = 19A$
 $C_{sen} = L / (Rocset * DCR)$
 $0.015uA / (10uA / (Rocset * 6m))$ Rocset=11.111K-11.8K
 $I_{ocp} = (Rocset * 10uA) / DCR$
 $I_{ocp} = (11K * 10uA) / (3.3m * 1.3) = 15.1A$



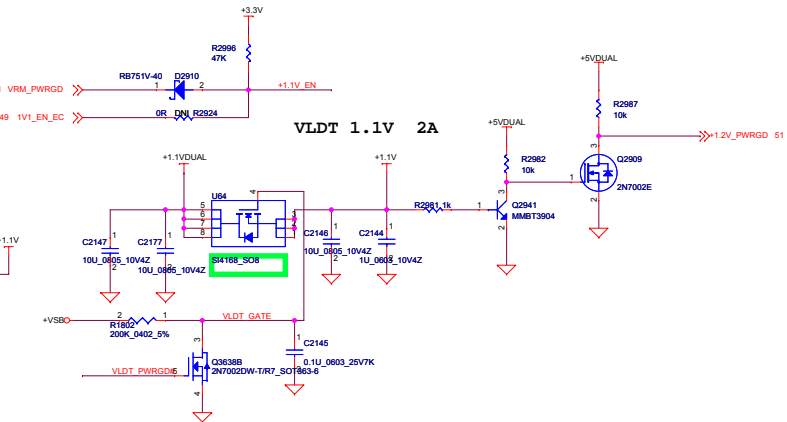
During Power Up
 $0 < 3.3V - 1.8V < 2.1V$

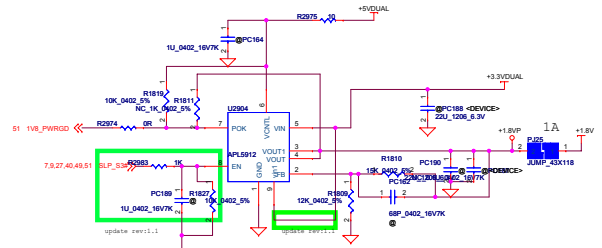


update on rev:1.1

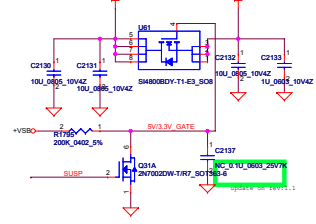
DCR 6m ohm(max) Cout ESR=15m ohm

$V_o = 0.6 * ((PR87 + PR83) / PR83) = 1.8V$
 $I_{peak} = 11.93A, I_{max} = 8.351A$
 $C_{sen} = L / (Rocset * DCR) = 1uF / (Rocset * 6m) = 0.022uF$
 $=> Rocset = 7.575K$, Choose 10K because of thermal factor
 $I_{ocp} = (Rocset * 10uA) / DCR = (10K * 10uA) / (0.006 * 1.3) = 12.82A$

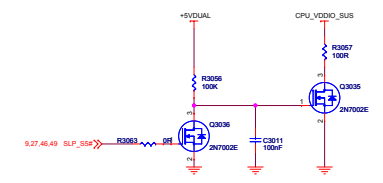
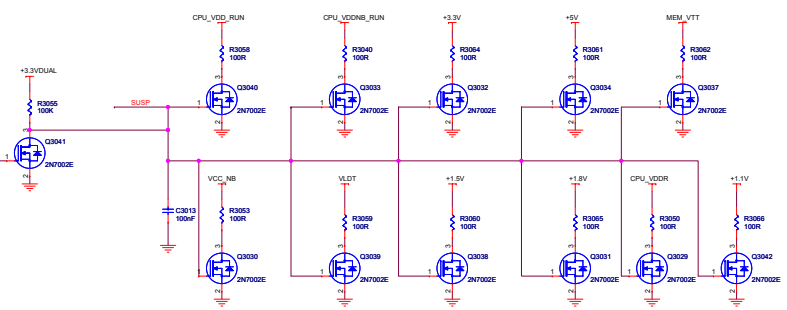
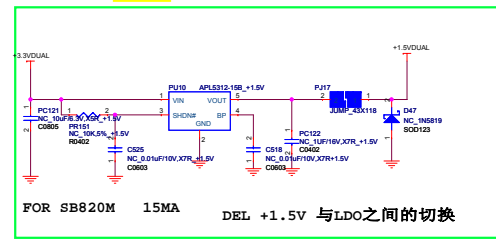
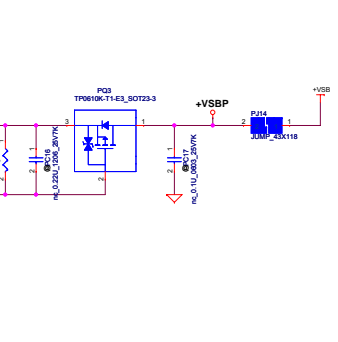
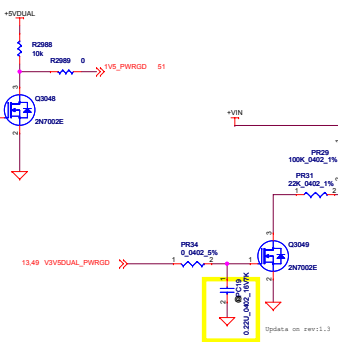
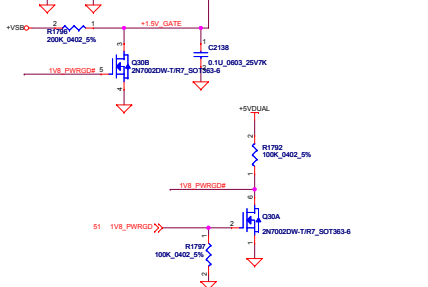
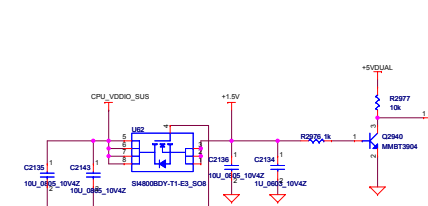
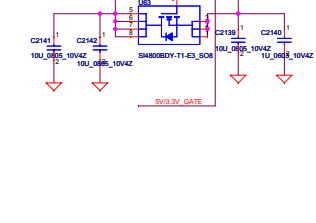




+5DUAL TO +5V



+3VDUAL TO +3.3V



5

4

3

2

1

D

D

C


C

B

B

A

A

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参数设定: Vo1=5.01V ;Vo2=3.3V

Update on rev:1.1

ADD RESISTOR TO GET -5% LOWER FOR +3.3V(3.1626V)

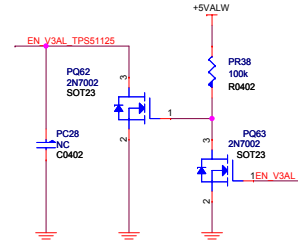
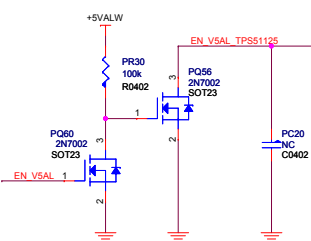
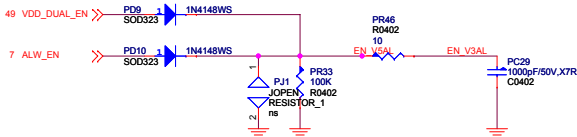
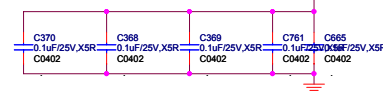
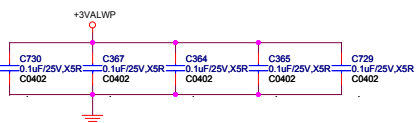
改变PR24取值, EN V3AL的网络

改变PR25取值, EN V5AL的网络

NOTE: H--> 5v
L--> 4.65V

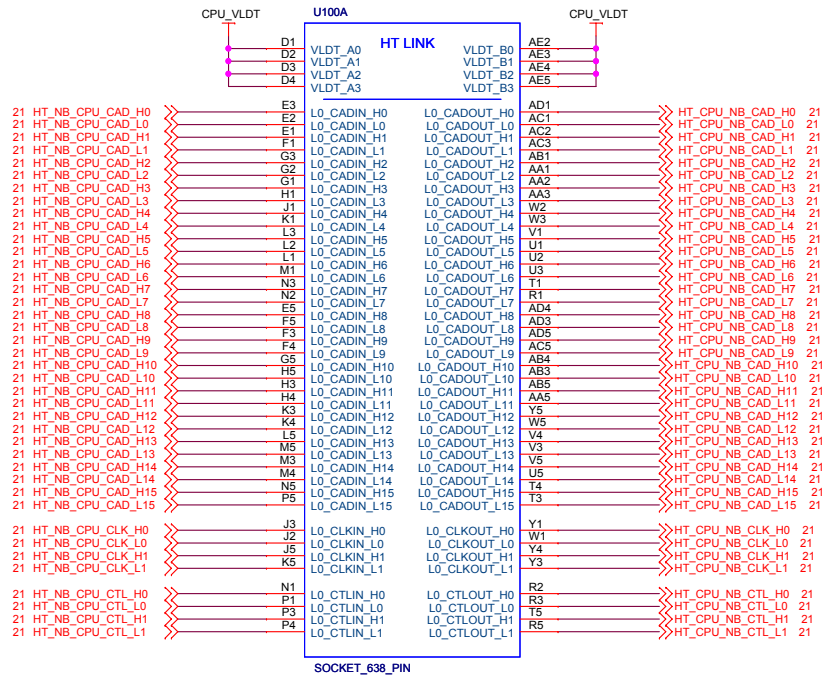
Iocp=10.8A

Iocp=9.7A

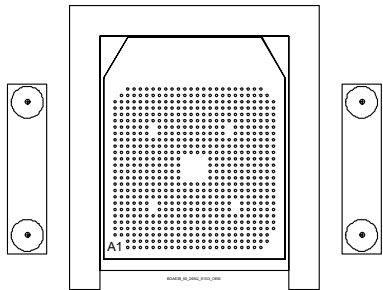
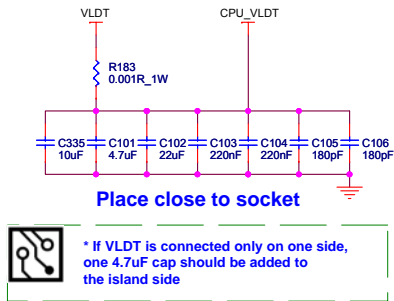


Add Enable/OCP Circuit 090918

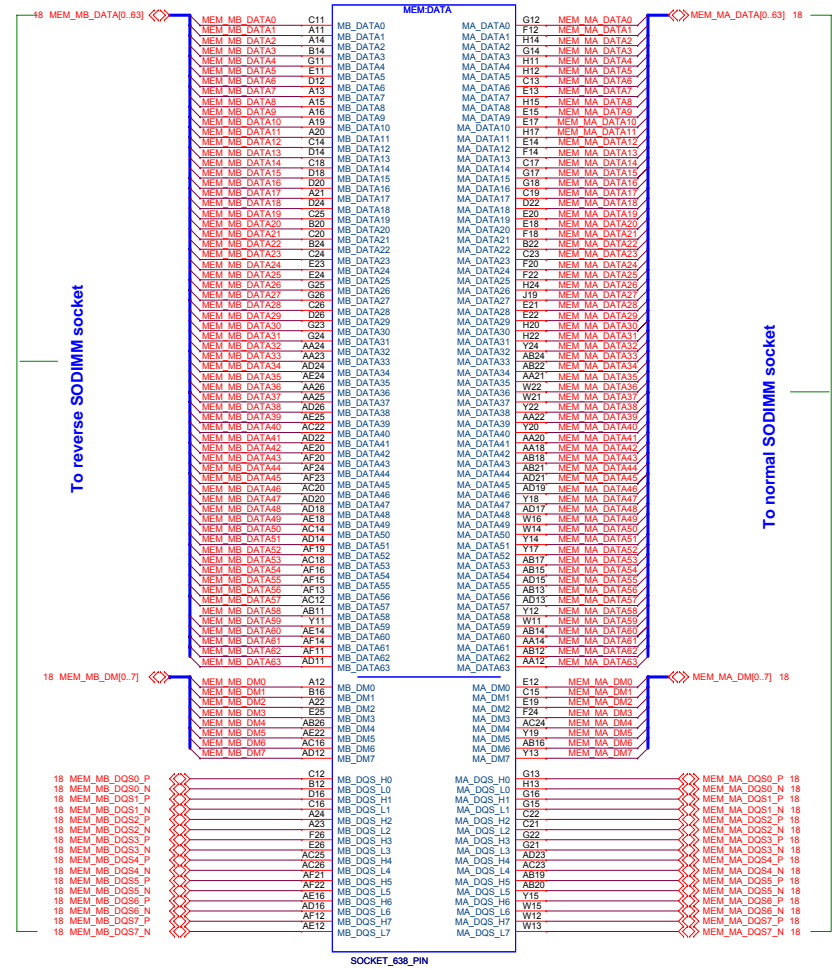
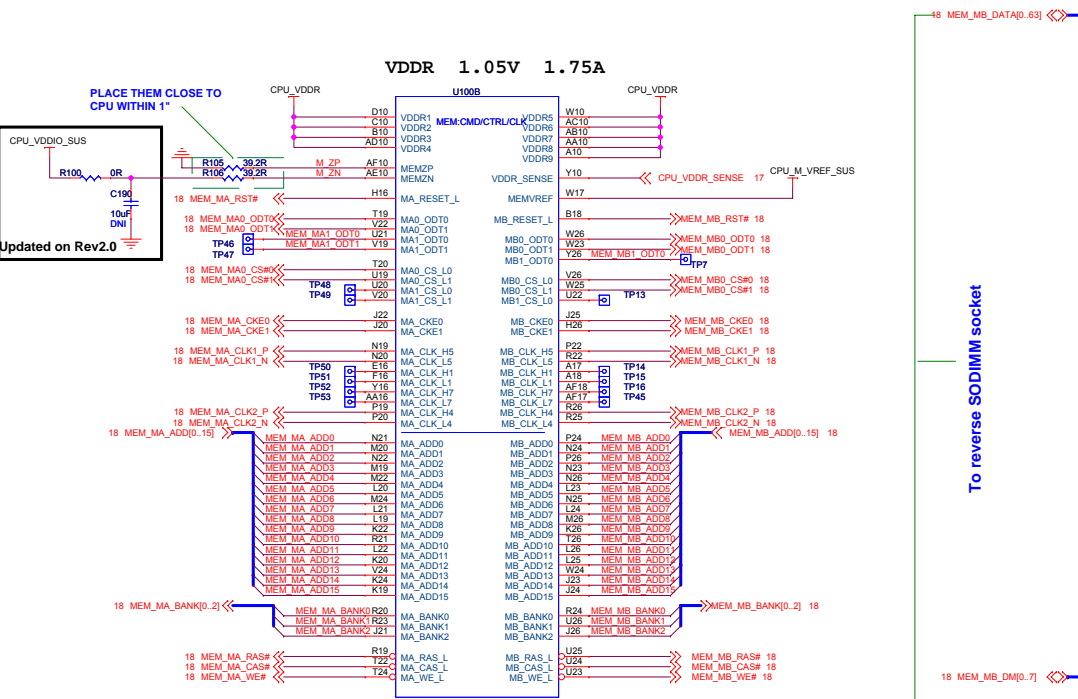
CPU_VLDT 1.1V 1.5A



DEL HTPA Soft-Touch Duo Connectors

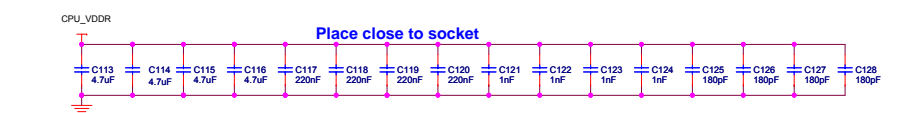
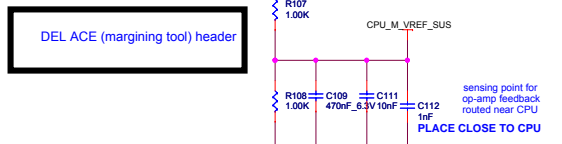


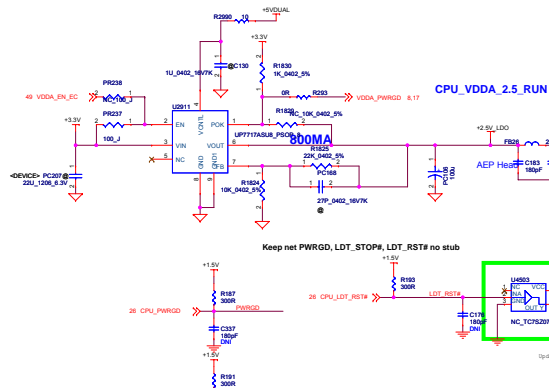
Processor Memory Interface



To reverse SODIMM socket

To normal SODIMM socket





LAYOUT: ROUTE VDDA TRACE APPROX. 20 mils WIDE (USE 0.25 mil TRACKS TO EXIT BALL FIELD) AND 500 mils LONG.

DEL
PLL bypass debug option
supports AC couple & DC bias

3.3V DEL SB-TSI HEADER

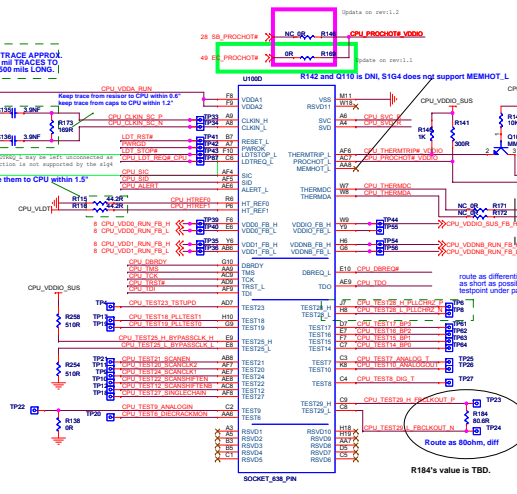
1.5V DEL SB-TSI HEADER

DEL AEP HEAD

DEL SCAN Connector

HDT pin24 can be VDDIO Level if only Purple Possum is used.
For old HDT tool, 3.3v level shift is required. However, Purple Possum can tolerance 3.3v.

HDT Connector



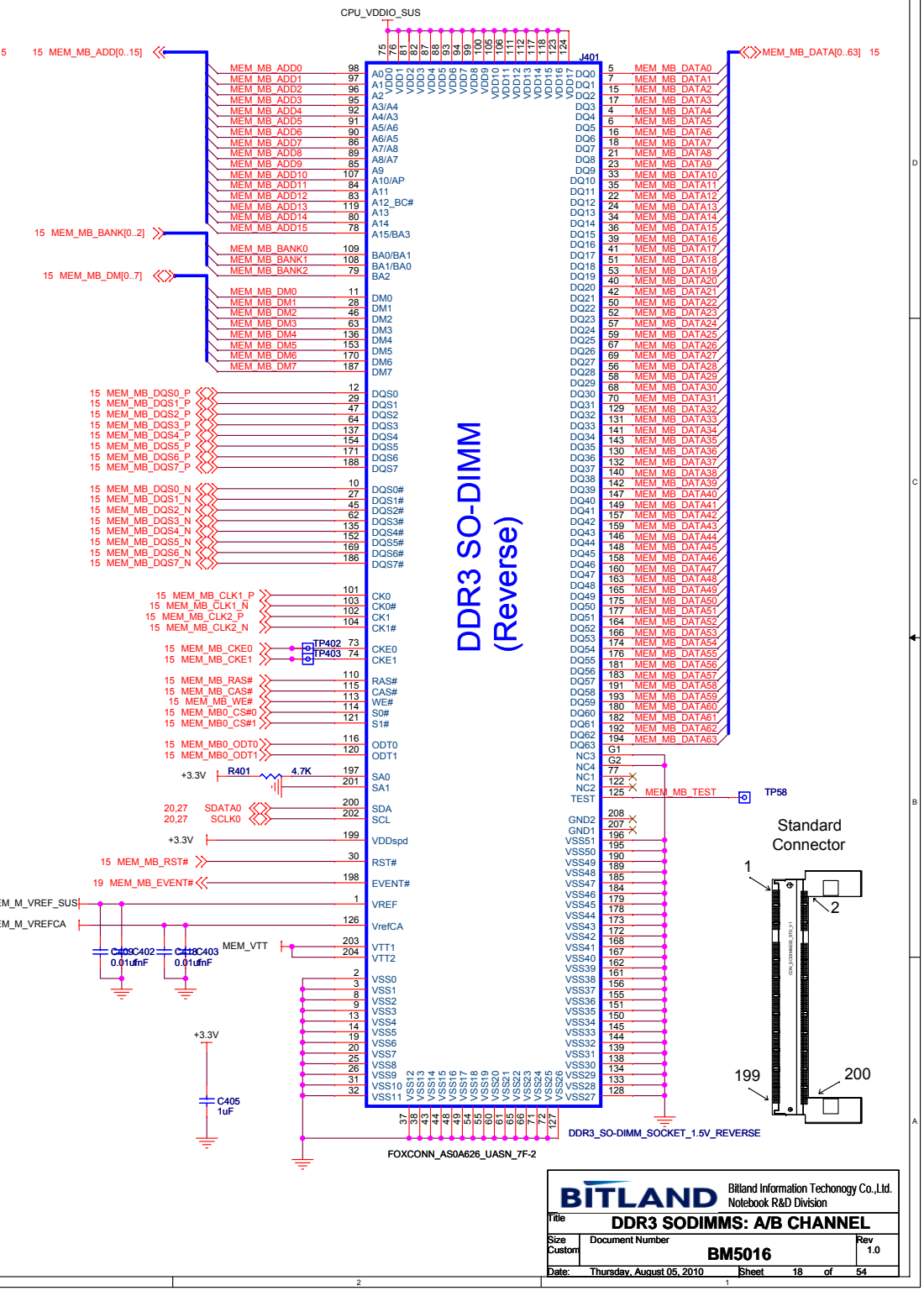
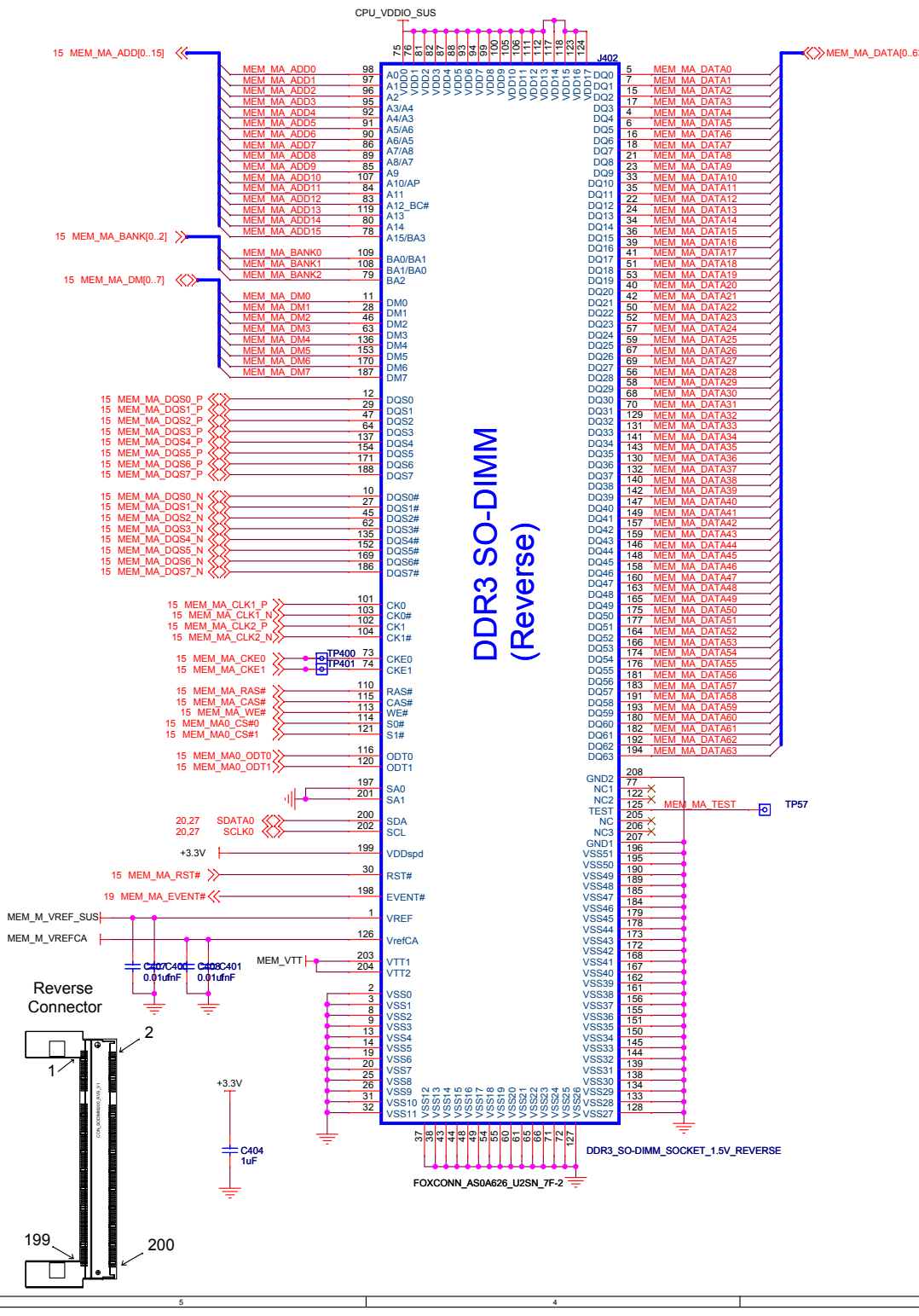
VID Override Circuit

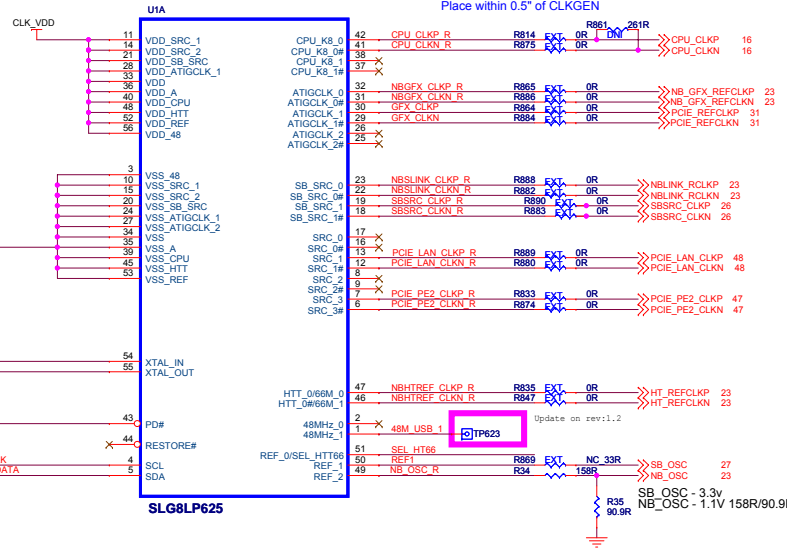
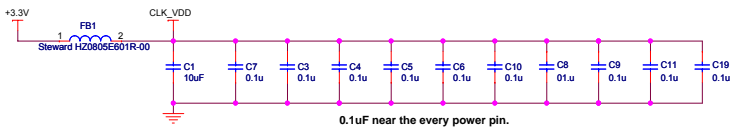
Note:
To override VID,
Remove R192, R194, R196, install R185
set VID via SW100

Use differential probing point open all switches

VID OVERRIDE TABLE (VDD)

SVC	SVD	BOOT VOLTAGE(VDD)	
		0.8V	1.0V
0	0	1.1	1.3
0	1	1.0	1.2
1	0	0.9	1.0
1	1	0.8	0.8





Clock chip has internal serial terminations for differential pairs, external resistors are reserved for debug purpose.

NB CLOCK INPUT TABLE

NB CLOCKS	RS740	RX780	RS790
HT_REFCLKP	6M SE(SINGLE END)	100M DIFF	100M DIFF
HT_REFCLKN	NC	100M DIFF	100M DIFF
REFCLK_P	14M SE (3.3V)	14M SE (1.8V)	14M SE (1.1V)
REFCLK_N	NC	NC	vref
GFX_REFCLK	100M DIFF	100M DIFF	100M DIFF(IN/OUT)*
GPP_REFCLK	NC	100M DIFF	NC or 100M DIFF OUTPUT
GPPSB_REFCLK	100M DIFF	100M DIFF	100M DIFF

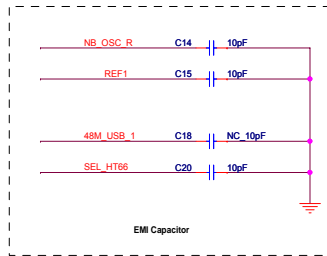
* RS790 can be used as clock buffer to output two PCIe reference clocks. By default, chip will configured as input mode, BIOS can program it to output mode.

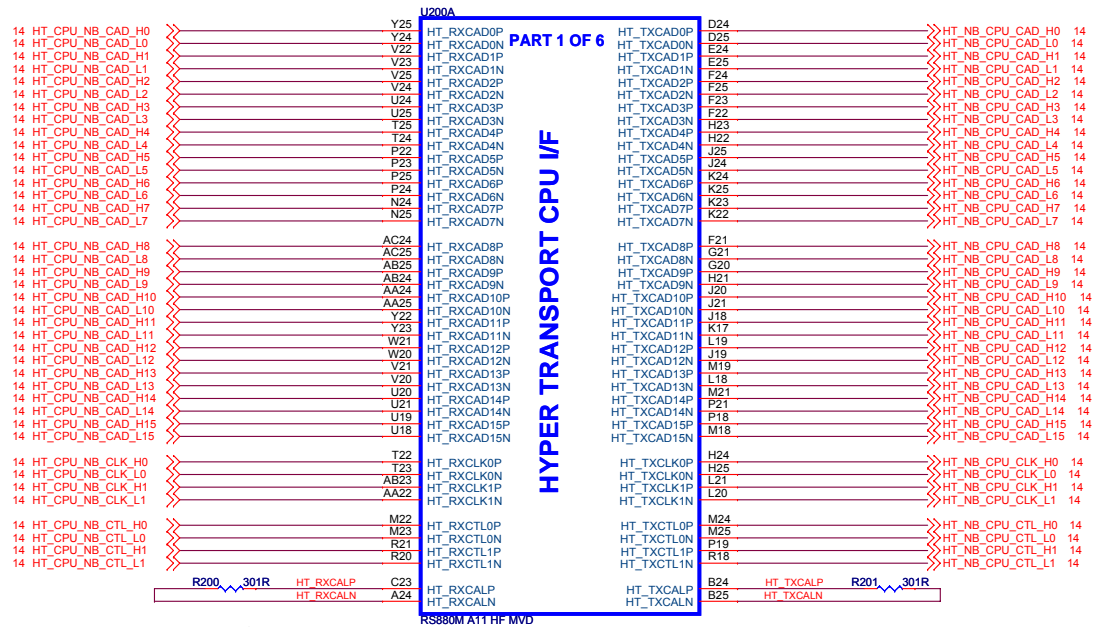
R34/R35 (value may change)

	OSC_14M_NB
RS740	3.3V 33R serial
RX780	1.8V 33R/43R
RS780	1.1V 200R/100R

SEL_HTT66	1	66 MHz 3.3V single ended HTT clock
	0*	100 MHz differential HTT clock
SEL_SATA	1*	100 MHz non-spreading differential SRC clock
	0	100 MHz spreading differential SRC clock

* default





BOM 为 300

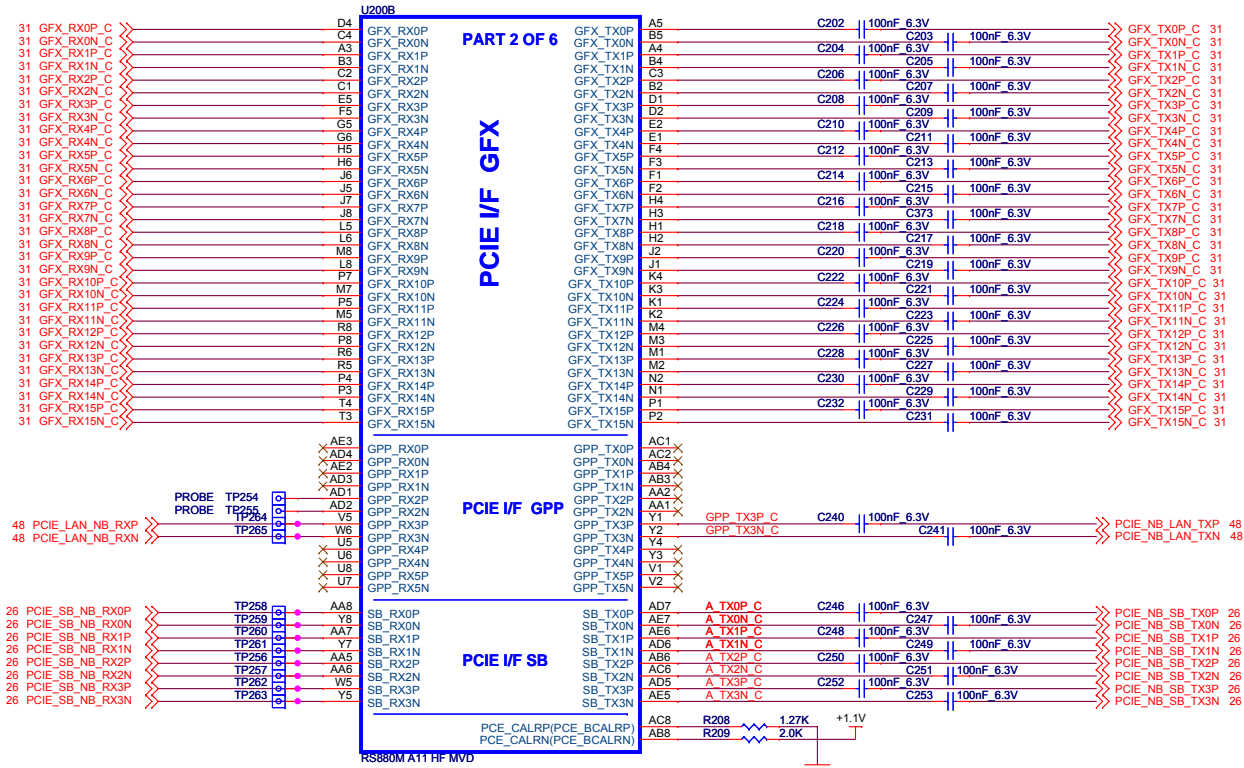
DEL HTPA PROBE CONNECTOR FOR DEBUG(NB SIDE)



MXM3.0 need put the CAP on the motherboard.
Close to the MXM Slot



MXM3.0 need put the CAP on the motherboard.
Close to the MXM Slot

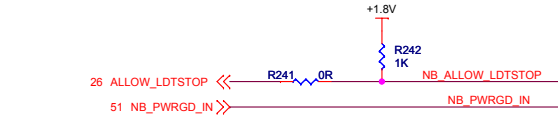
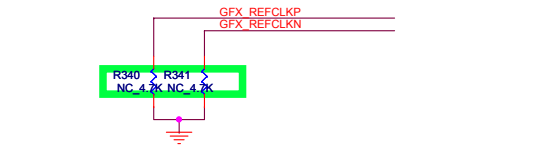
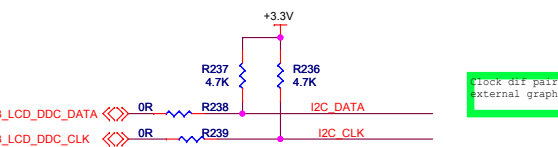
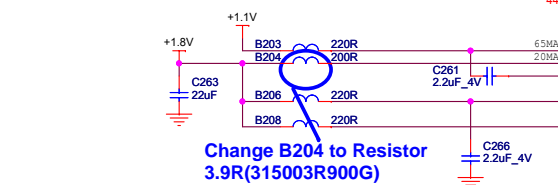
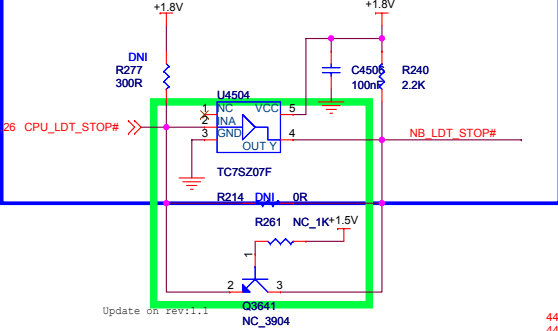


Keep the impedance of PCIE lane to 85ohm +/-15%
Including the A-link

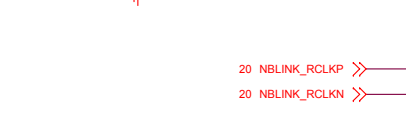
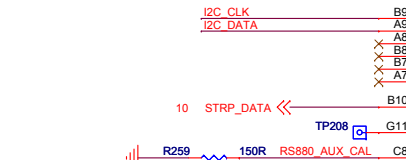
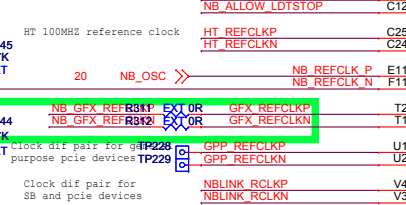
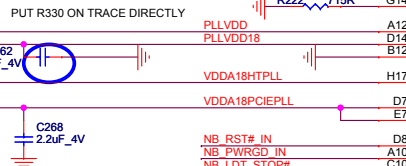
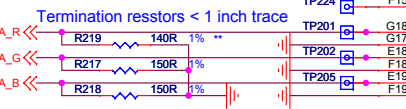
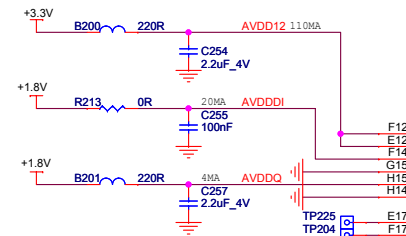


All PCIE lane shou route 8" max for Gen2 connector and max 12" for Gen2 on board devices
Guam has the Lasso lane over 8" due to the large board, should use shorter lasso calbe for Guam.
Customer need to follow the MBDG.

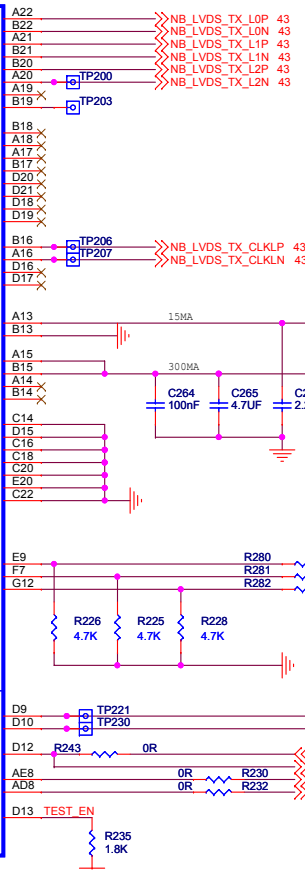
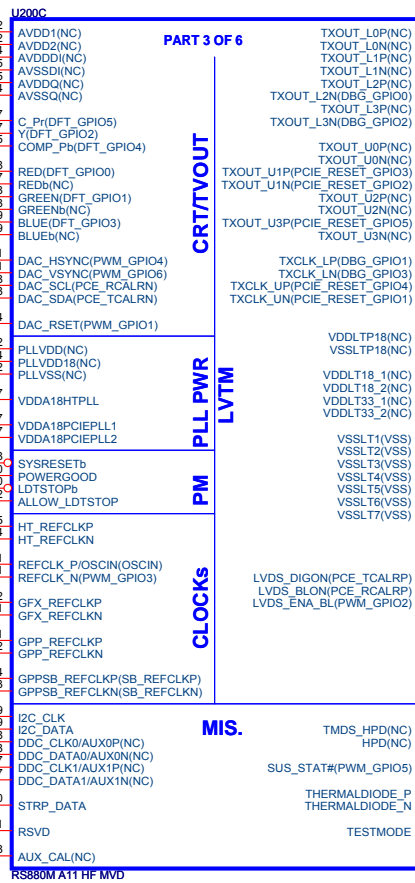
Note:Regarding LDT_STOP# signal,It's required within 40ns skew for both assertion and de-assertion between NB and CPU.



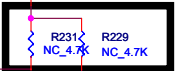
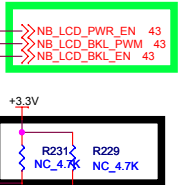
DEL
RS880M UVD DEBUG HEAD
RS880M JTAG
8BIT DEBUG HEADER



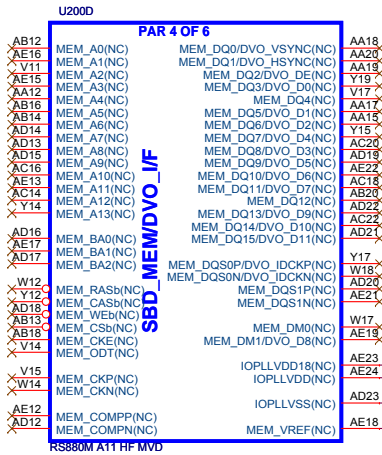
PLACE R291, R292 CLOSE TO NB(R291, R292 IS FOR A11 SB800 ONLY)



DEL THERMAL SENSOR

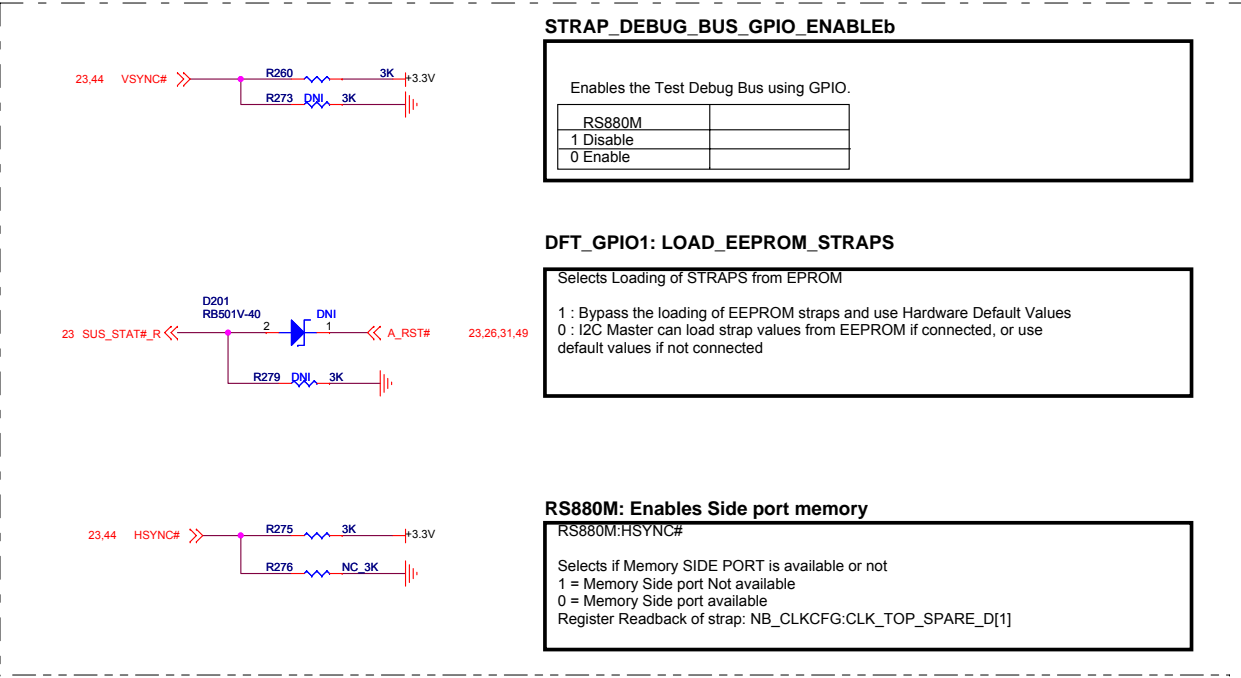
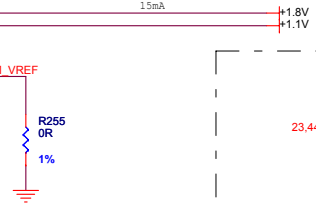


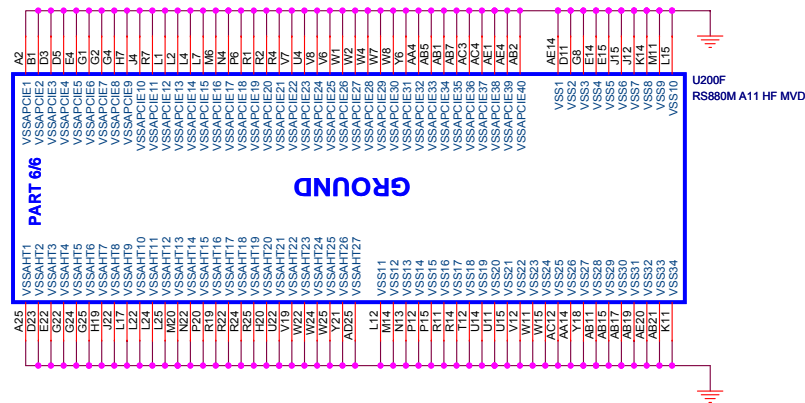
- 20 HT_REFCLKP
- 20 HT_REFCLKN
- 20 NB_GFX_REFCLKP
- 20 NB_GFX_REFCLKN



DEL SDRAM DDR3

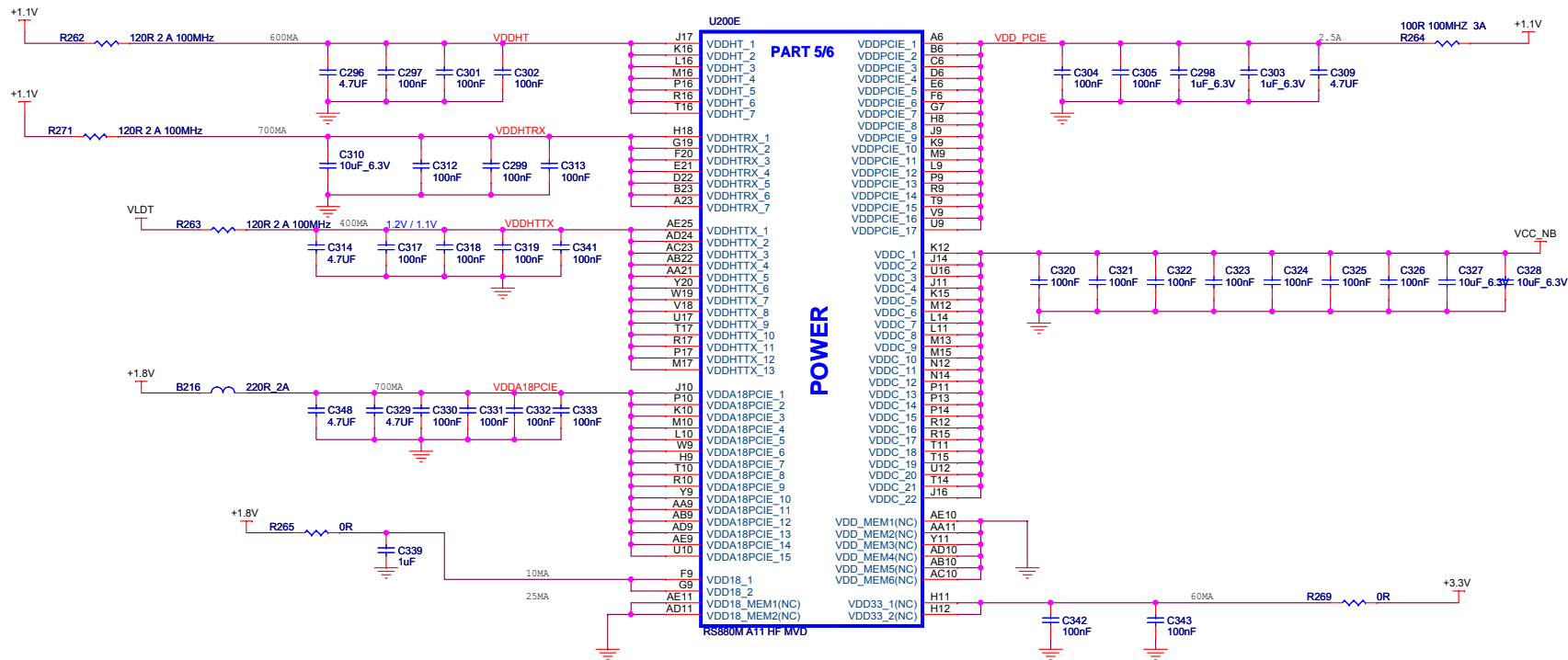
DEL U202





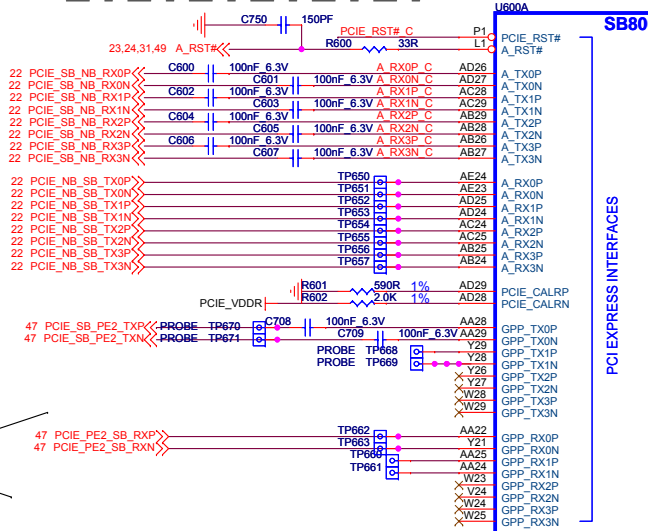
RS880M POWER TABLE

PIN NAME	RS880M	PIN NAME	RS880M
VDDHT	+1.1V	IOPLLVD	+1.1V
VDDHTRX	+1.1V	AVDD	+3.3V
VDDHTTX	+1.2V	AVDDI	+1.8V
VDDA18PCIE	+1.8V	AVDDQ	+1.8V
VDDG18	+1.8V	PLLVD	+1.1V
VDD18_MEM	+1.8V	PLLVD18	+1.8V
VDDPCIE	+1.1V	VDDA18PCIEPLL	+1.8V
VDDC	+1.1V	VDDA18HTPLL	+1.8V
VDD_MEM	+1.8V/1.5V	VDDLTP18	+1.8V
VDDG33	+3.3V	VDDL18	+1.8V
IOPLLVD18	+1.8V	VDDL33	NC



DEL FAN CIRCUIT

PLACE THESE PCIE AC COUPLING CAPS CLOSE TO U600



J613 CLOSE TO U600

NOTE: SB8XX ONLY SUPPORTS 2 GPP PORT 2 AND 3 IS NOT SUPPORTED.

NOTE: The 0R serial resistor on SB CLK pair must share Pin Pad with the serial resistor close to U600

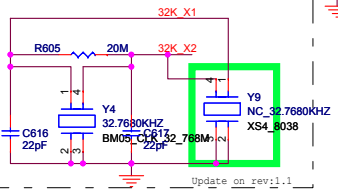
FOR EXT GRAPHICS

FOR WIFI

FOR LAN

Updated on Rev2.0

PLACE THESE COMPONENTS CLOSE TO U600, AND USE GROUND GUARD FOR 32K_X1 AND 32K_X2



SB_GPP GFX_CLK	DEVICE	CLKREQ#	CLK_REQG#
0	//		
1	PE0	1	1
2	PE2	2	2
3	LAN	3	3
4	PE1	4	4
5	//	5	5
6	PE3	6	6
7	//	7	7
8	//	8	8

SB800 Part 1 of 5

PCIE EXPRESS INTERFACES

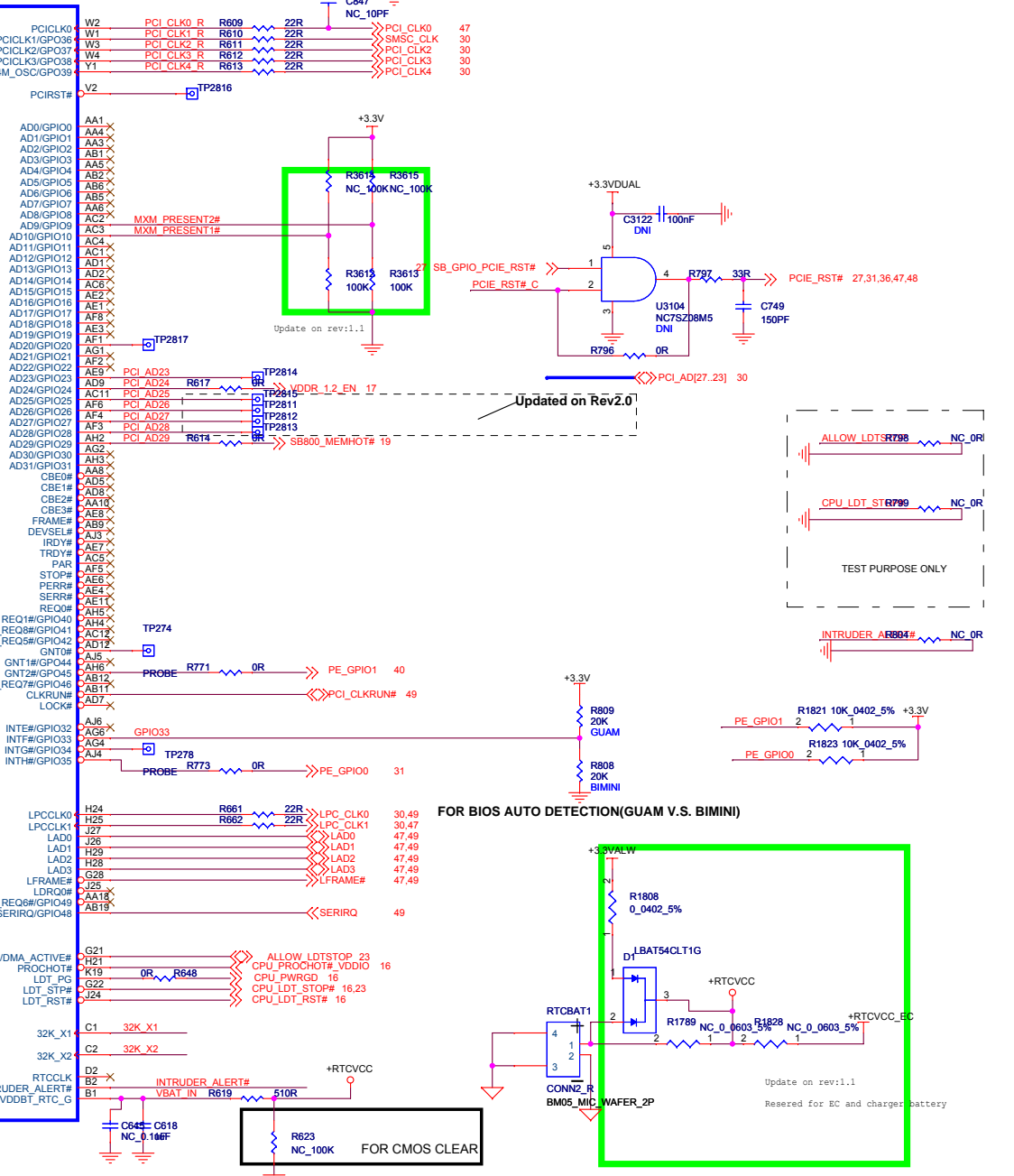
PCIE INTERFACE

CLOCK GENERATOR

LPC

CPU

RTC



POWER EXPRESS SUPPORT

PE_GPIO0 MXM RESET H: Enable

PE_GPIO1 MXM POWER ENABLE H: Enable

PE_GPIO2 MODE SWITCH(BY NB) H:MXM L:NB

TMSD_HP0D MXM HOT PLUG

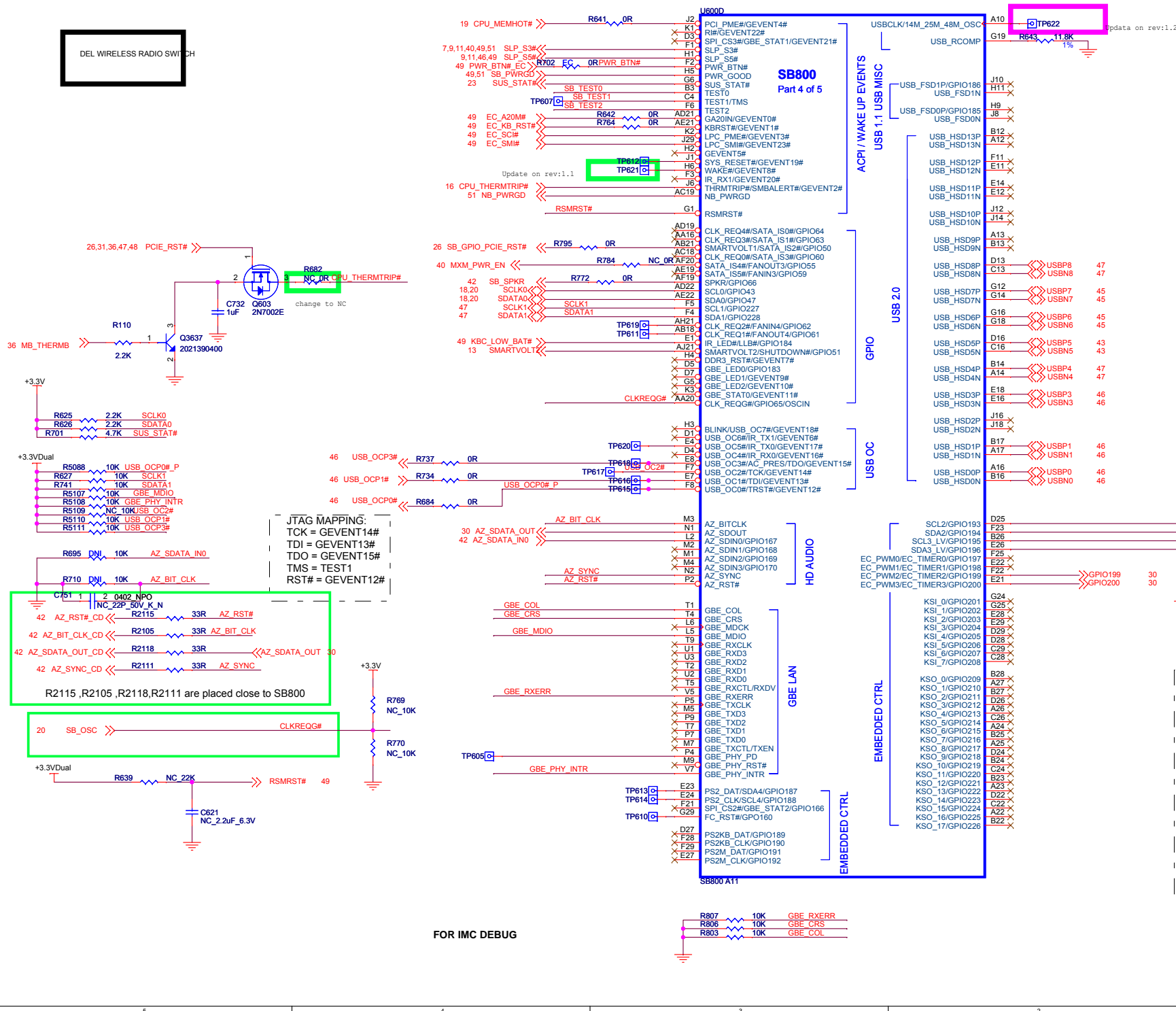
BITLAND Bitland Information Technology Co., Ltd.
Notebook R&D Division

Title: **SB8X0-PCIE/PCI/CPU/LPC/CLK**

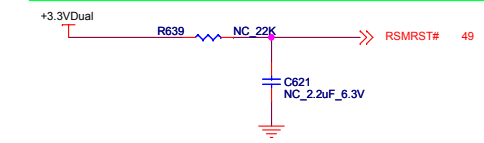
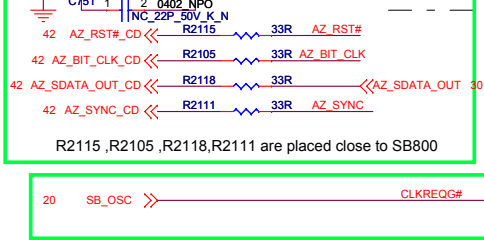
Size: Custom Document Number: **BM5016** Rev: 1.0

Date: Thursday, August 05, 2010 Sheet: 26 of 54

DEL WIRELESS RADIO SWITCH

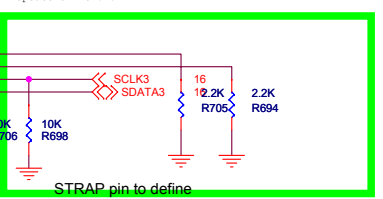


JTAG MAPPING:
 TCK = GEVENT14#
 TDI = GEVENT13#
 TDO = GEVENT15#
 TMS = TEST1
 RST# = GEVENT12#

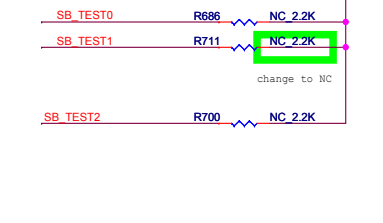


FOR IMC DEBUG

- USB15 NA
- USB14 NA
- USB13 NA
- USB12 NA
- USB11 NA
- USB10 NA
- USB9 NA
- USB8 3G PCIE Mini Slot
- USB7 Blue Tooth
- USB6 Finger Print
- USB5 CAM
- USB4 WIFI PCIE MINI SLOT
- USB3 USB PORT3
- USB2 NC
- USB1 USB PORT1
- USB0 USB PORT0



TEST2	TEST1	TEST0	TEST MODE	DESCRIPTION
0	0	0	None	Normal operation.
0	0	1	Reserved	Reserved for ASIC debug
0	1	X	Test mode	Enable Test Mode
1	X	X	Reserved	Reserved for ASIC debug



SB800 SB_TEST0,SB_TEST1,SB_TEST2 has internal 10K PD.

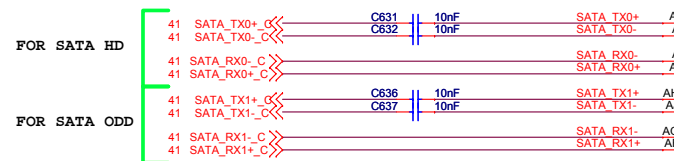
BITLAND Bitland Information Technology Co., Ltd.
 Notebook R&D Division

Title: **SB8X0-GPIO/USB/AZ/RGMII**

Size Custom Document Number: **BM5016** Rev 1.0

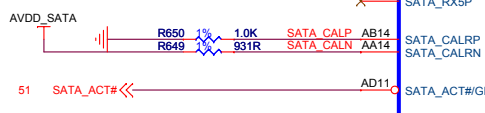
Date: Thursday, August 05, 2010 Sheet 27 of 54

SATA trace should use only 1via on the trace. customers can use 2vias with GND via within 150mils of signal via as long as they can ensure that their platform meets SATA logo requirements. Return loss is expected to get affected with 2 vias. AMD platforms are validated with one via only

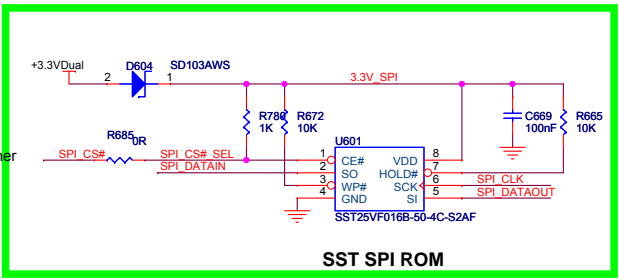
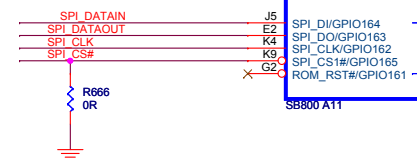
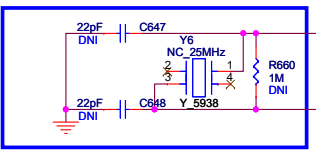


- SATA PORTS DISTRIBUTION:
- 0, - 2.5 INCH DISK DRIVER
 - 1, SATA, ODD
 - 2, NOT USED
 - 3, NOT USED
 - 4 & 5, NOT USED

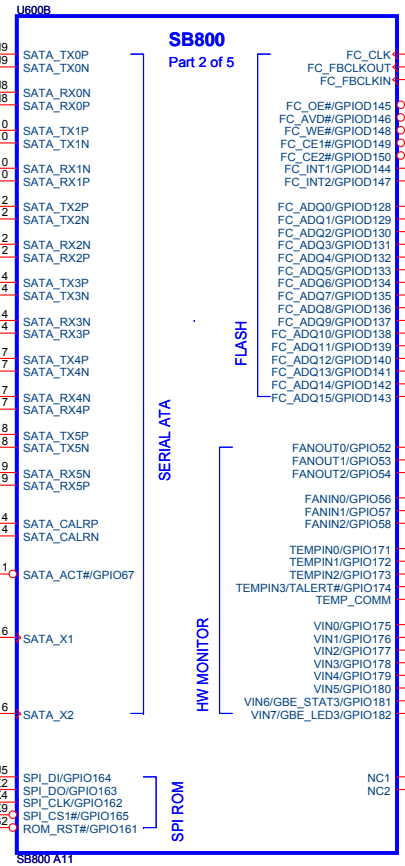
PLACE SATA_CAL RES VERY CLOSE TO BALL OF U600



To meet SB800 SCL1.02: DNI SATA XTAL circuit's parts



change to SPI mode



FLASH

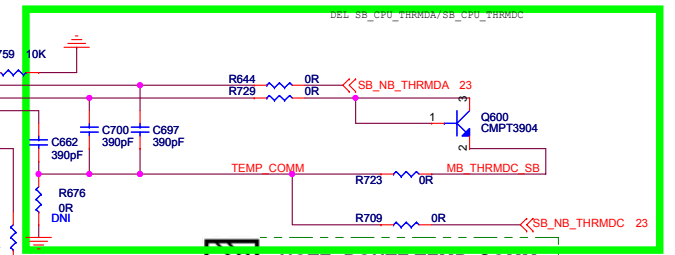
SERIAL SATA

HW MONITOR

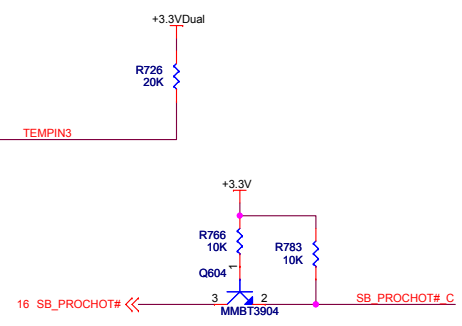
SPI ROM

SB800 Part 2 of 5

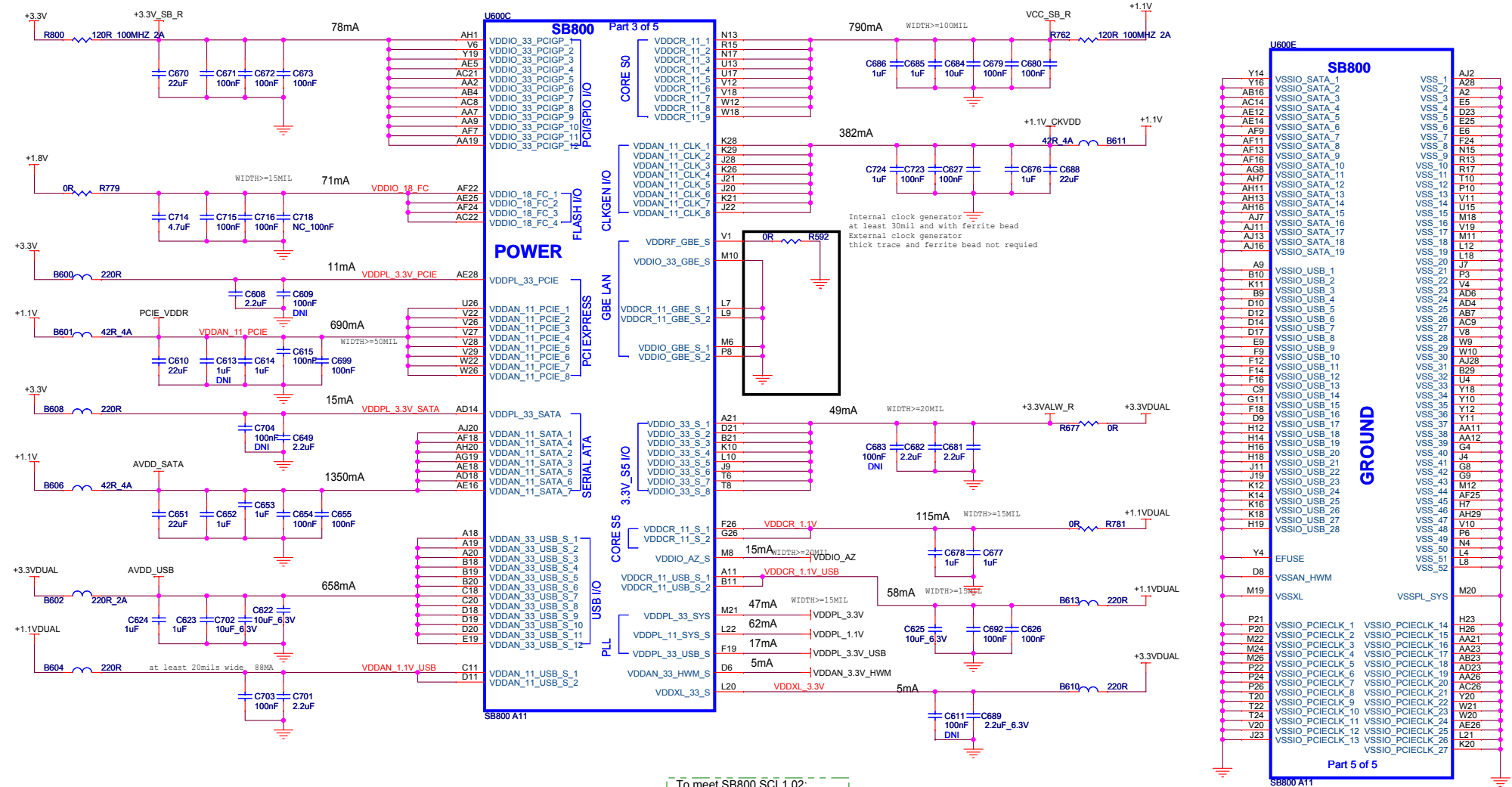
Connect C7 and D8, then go to GND directly.



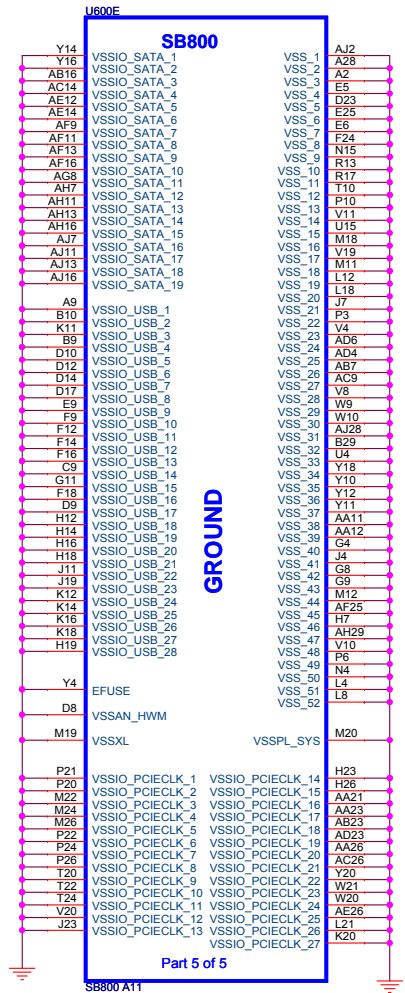
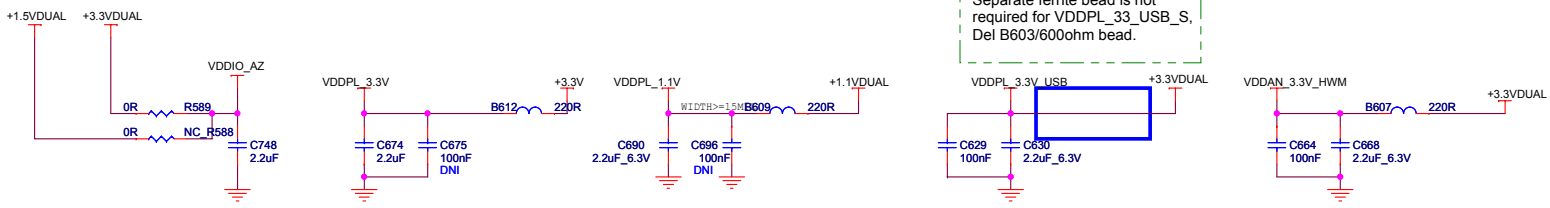
NOTE: ROUTE TEMP_COMM AS A 10MIL TRACE



PLACE ALL THE DECOUPLING CAPS ON THIS SHEET CLOSE TO SB AS POSSIBLE.

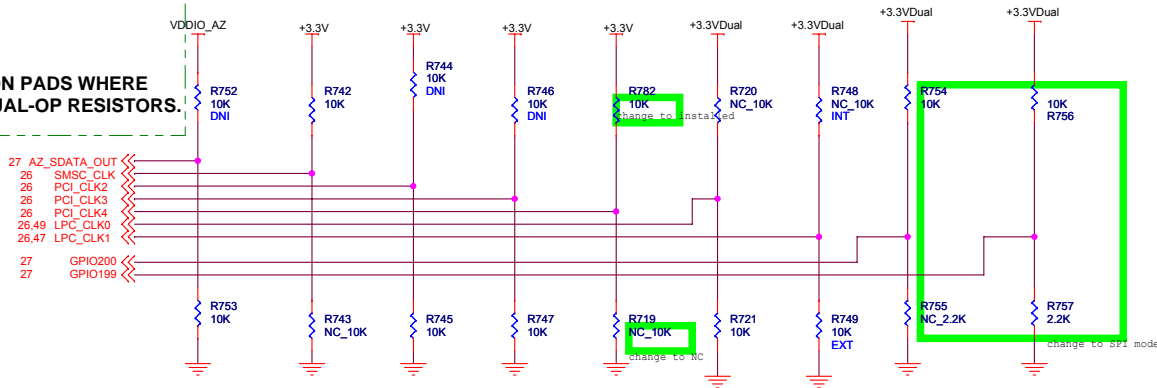


To meet SB800 SCL1.02:
Separate ferrite bead is not required for VDDPL_33_USB_S, Del B603/600ohm bead.





OVERLAP COMMON PADS WHERE POSSIBLE FOR DUAL-OP RESISTORS.



DEL JTAG HEADER

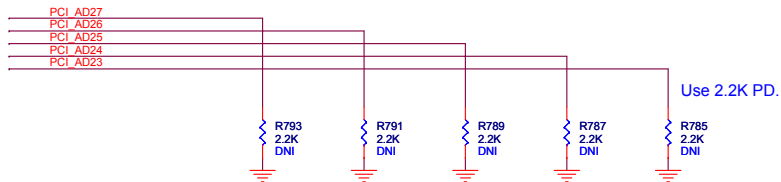
REQUIRED STRAPS

	AZ_SDOOUT	SMSC_CLK	PCI_CLK2	PCI_CLK3	PCI_CLK4	LPC_CLK0	LPC_CLK1	GPIO200	GPIO199
PULL HIGH	LOW POWER MODE	ALLOW PCIE Gen2 DEFAULT	Watchdog Timer Enabled	USE DEBUG STRAP	non_Fusion CLOCK MODE DEFAULT	EC ENABLED	CLKGEN ENABLED DEFAULT	H,H = Reserved H,L = SPI ROM	
PULL LOW	PERFORMANCE MODE DEFAULT	FORCE PCIE Gen1	Watchdog Timer Disabled DEFAULT	IGNORE DEBUG STRAP DEFAULT	FUSION CLOCK MODE	EC DISABLED DEFAULT	CLKGEN DISABLED	L,H = LPC ROM (Default) L,L = FWH ROM	

DEBUG STRAPS

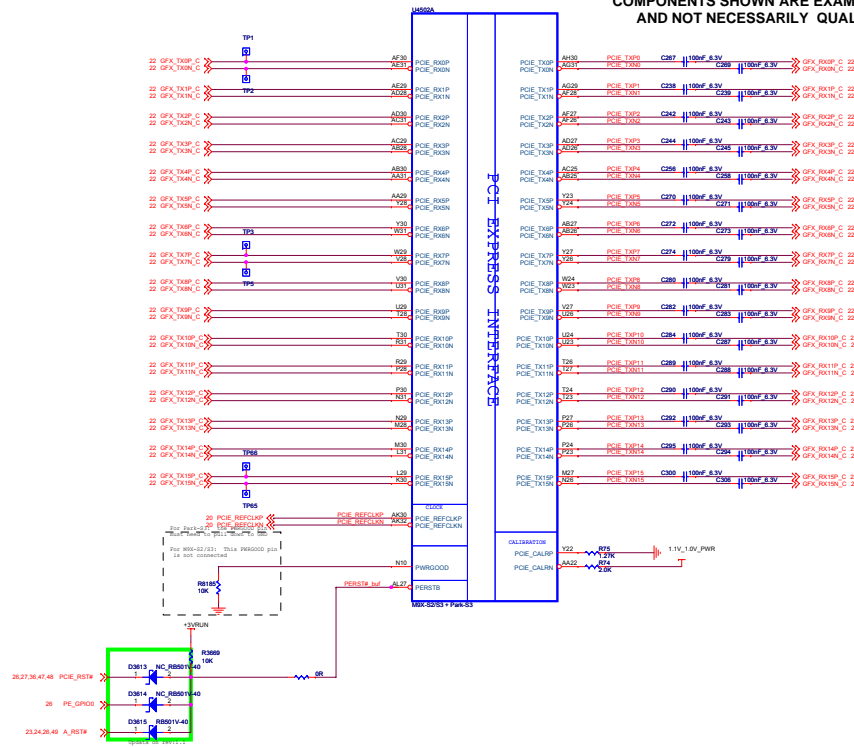
SB800 HAS 15K INTERNAL PU FOR PCI_AD[27:23]

26 PCI_AD[27..23] <<>



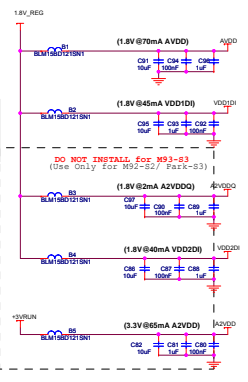
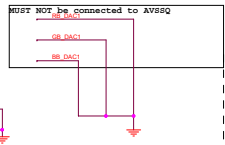
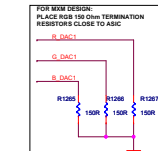
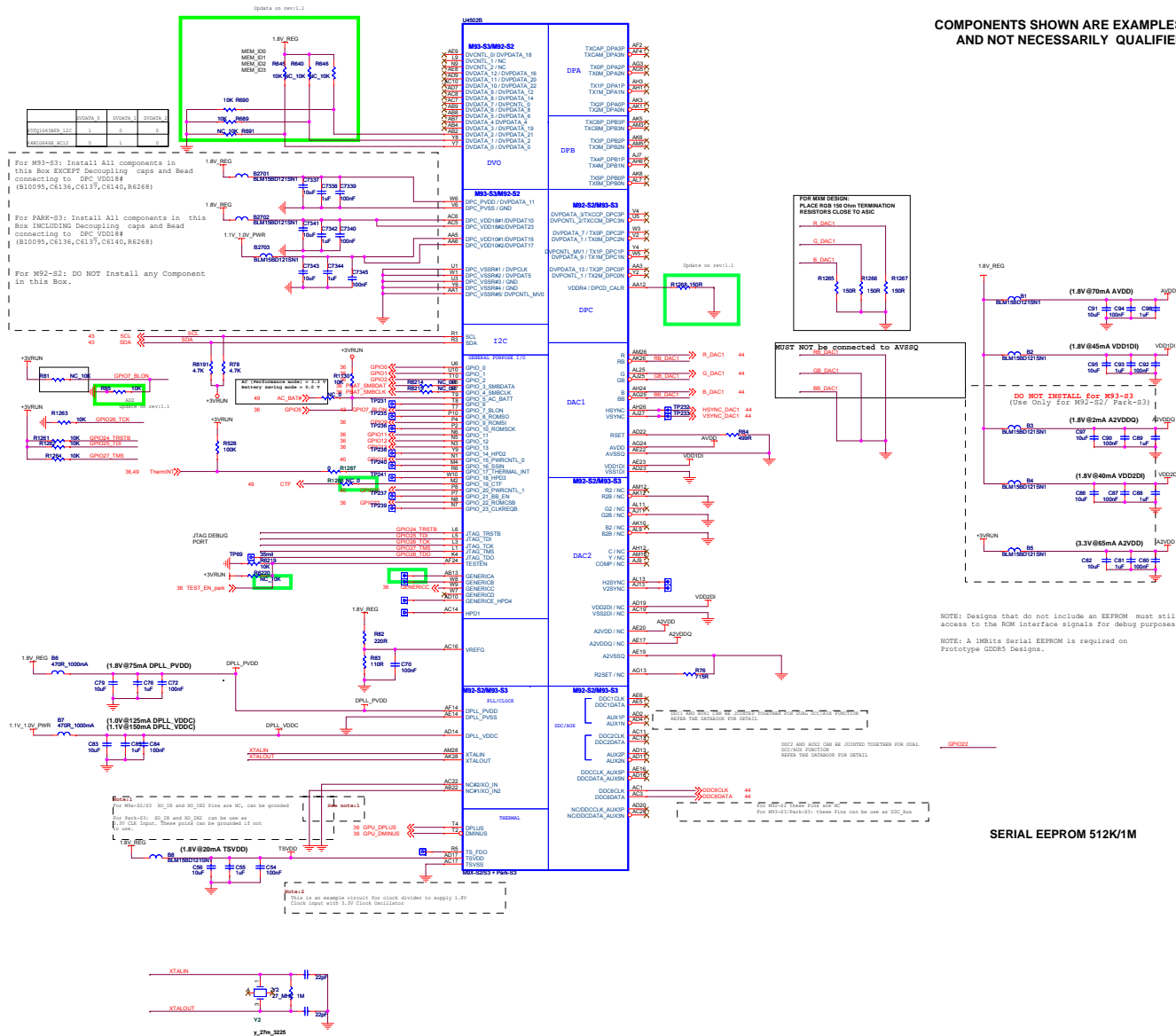
	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23
PULL HIGH	USE PCI PLL DEFAULT	DISABLE ILA AUTORUN DEFAULT	USE FC PLL DEFAULT	USE DEFAULT PCIE STRAPS DEFAULT	DISABLE PCI MEM BOOT DEFAULT
PULL LOW	BYPASS PCI PLL	ENABLE ILA AUTORUN	BYPASS FC PLL	USE EEPROM PCIE STRAPS	ENABLE PCI MEM BOOT

COMPONENTS SHOWN ARE EXAMPLES ONLY
AND NOT NECESSARILY QUALIFIED



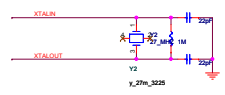
COMPONENTS SHOWN ARE EXAMPLES ONLY
AND NOT NECESSARILY QUALIFIED

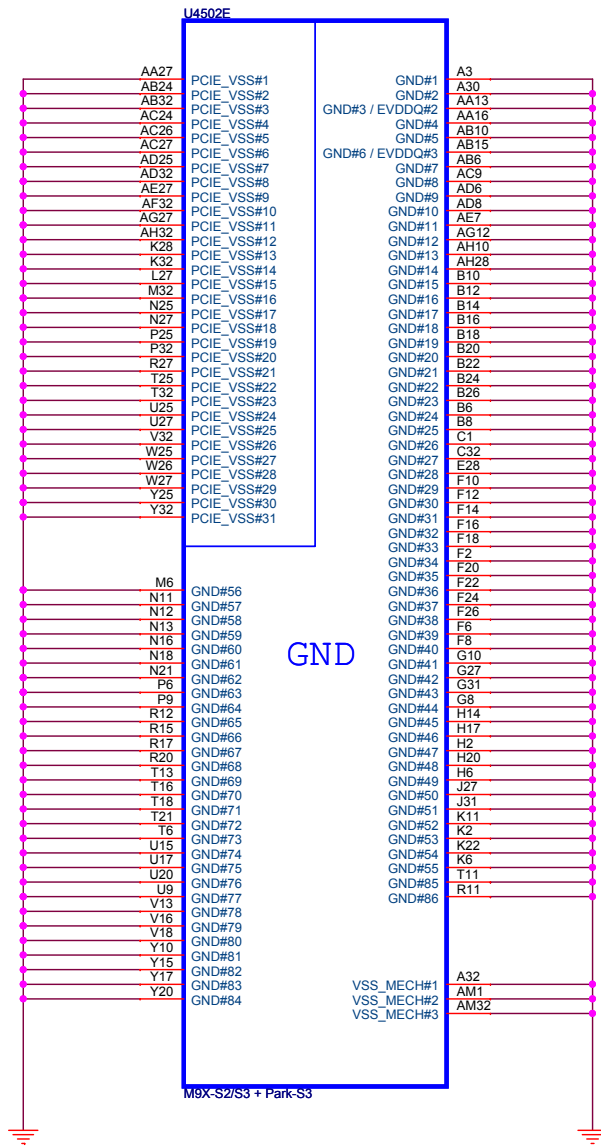
COMPONENTS SHOWN ARE EXAMPLES ONLY
AND NOT NECESSARILY QUALIFIED



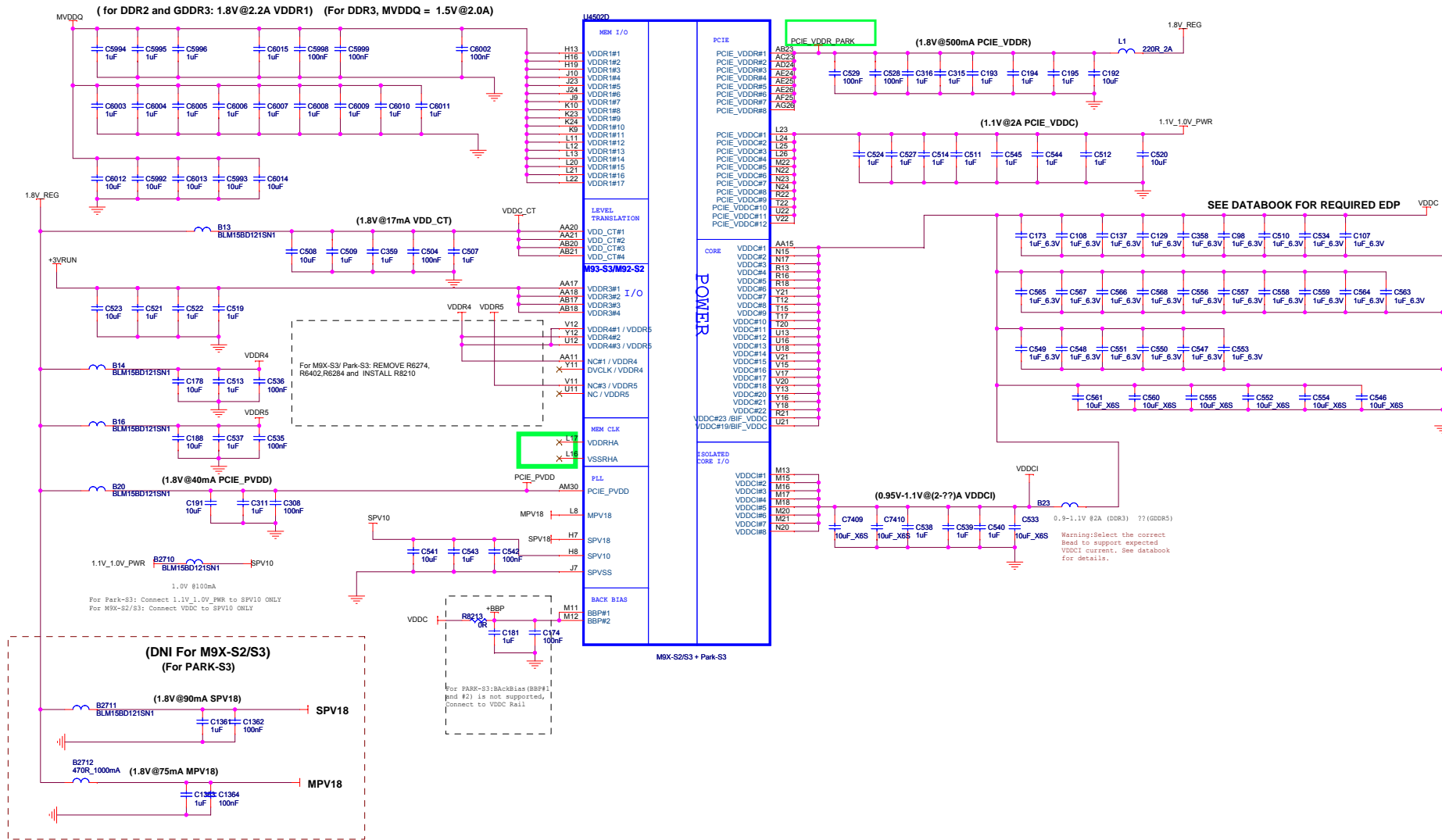
NOTE: Designs that do not include an EEPROM must still provide access to the ROM interface signals for debug purposes.
NOTE: A 1Mbit Serial EEPROM is required on Prototype GDR5 Designs.

SERIAL EEPROM 512K/1M

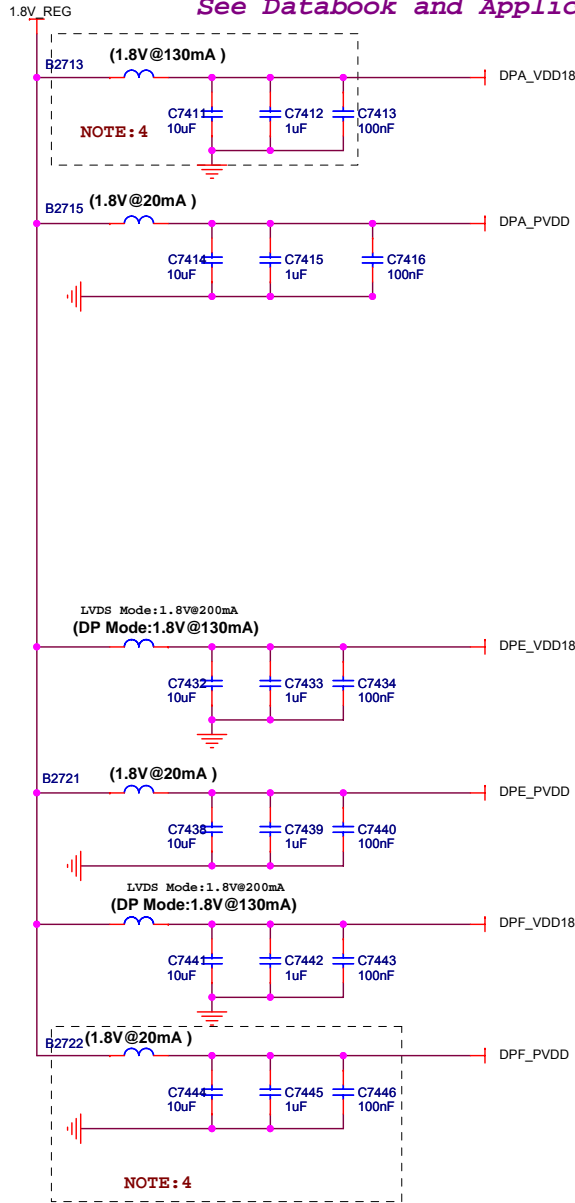




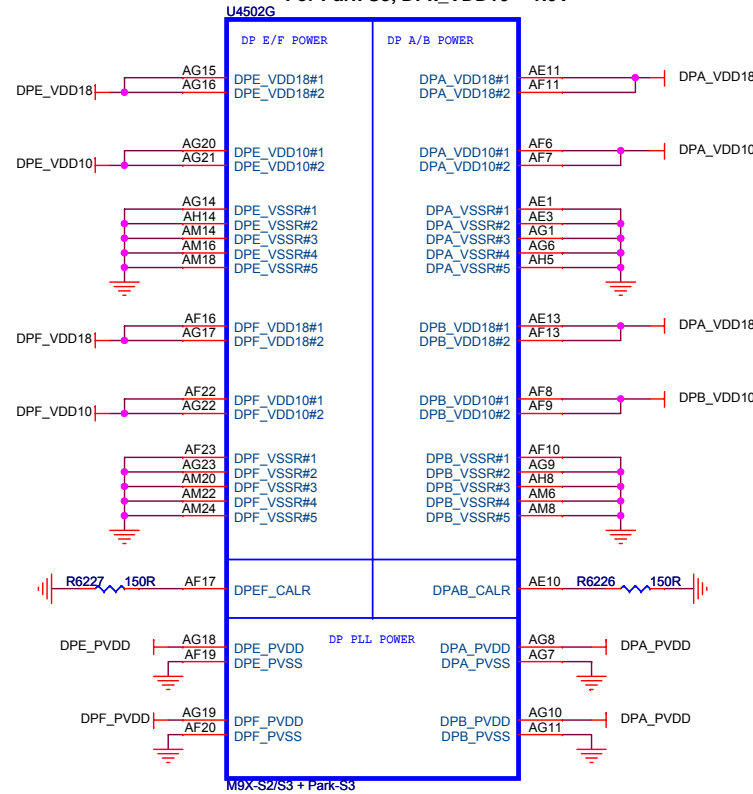
BITLAND		Bitland Information Technology Co., Ltd. Notebook R&D Division	
Title PARK-XT(Core_GND)			
Size	Document Number	Rev	
B	BM5016	1.0	
Date:	Thursday, August 05, 2010	Sheet	33 of 54



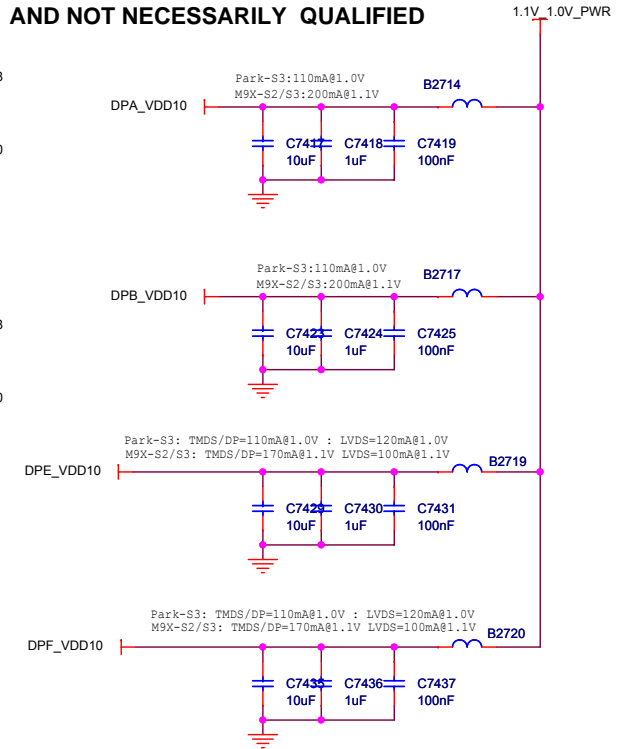
See Databook and Application note table for Voltage and Current requirements for each individual rail.



For M9X-S2/S3, DPx_VDD10 = 1.1V
For Park-S3, DPx_VDD10 = 1.0V



COMPONENTS SHOWN ARE EXAMPLES ONLY
AND NOT NECESSARILY QUALIFIED



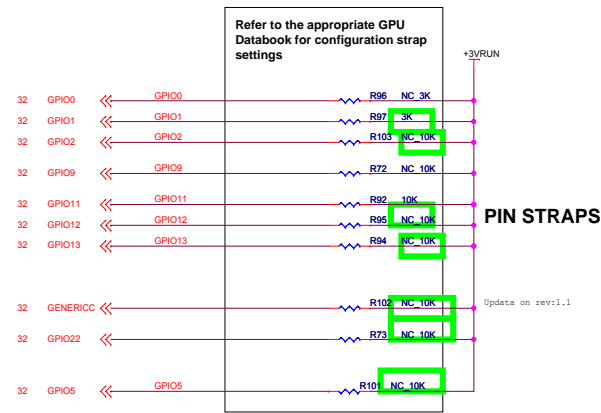
NOTE:1: DPx_VDD18 and DPx_PVDD Rails can be join together and remove Decoupling Capacitors and BEAD for DPx_PVDD if signal integrity for DP lanes are OK.

NOTE:2: DPA_VDD10 / DPB_VDD10 and DPE_VDD10 / DPF_VDD10 Rails can be join together and remove Decoupling Capacitors and BEAD for one rail of each pair if signal integrity for DP lanes are OK. We also need to Change BEAD to minimum 400mA rating.

NOTE:3: DPx_VDD18 Rails can be join together as shown in schematic for Dual -Link DVI or LVDS setting and remove Decoupling Capacitors and BEAD of any one rail of the pair if signal integrity for DP lanes are OK. We need atleast 500mA Bead to support join rails.

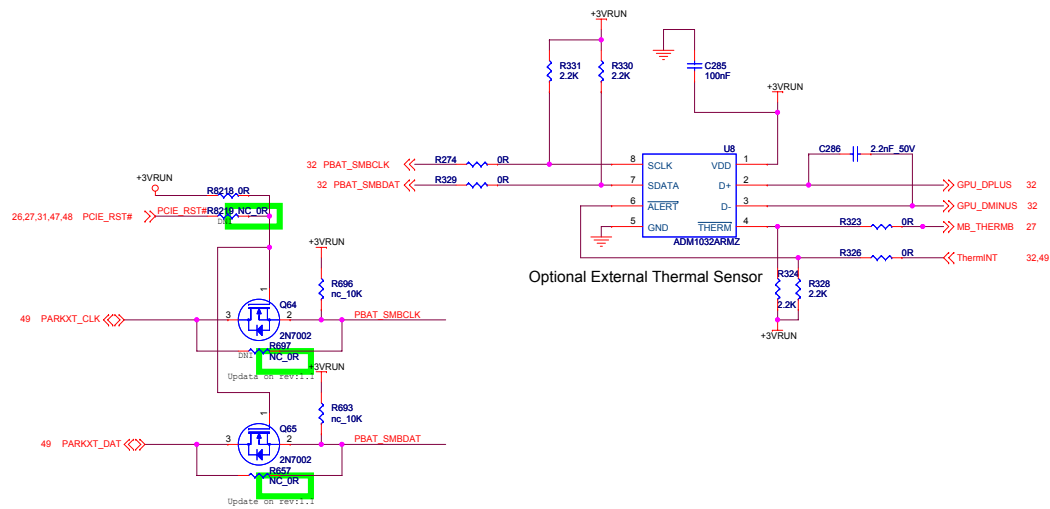
NOTE:4: Do not Install for M9X-S2/S3. INSTALL ONLY for PARK-S3. Other Notes can be apply as well.

BITLAND		Billand Information Technology Co.,Ltd. Notebook R&D Division	
Title: Park-XT(DP Power)			
Size	Document Number	Rev	1.0
B	BM5016		
Date:	Thursday, August 05, 2010	Sheet	35 of 54

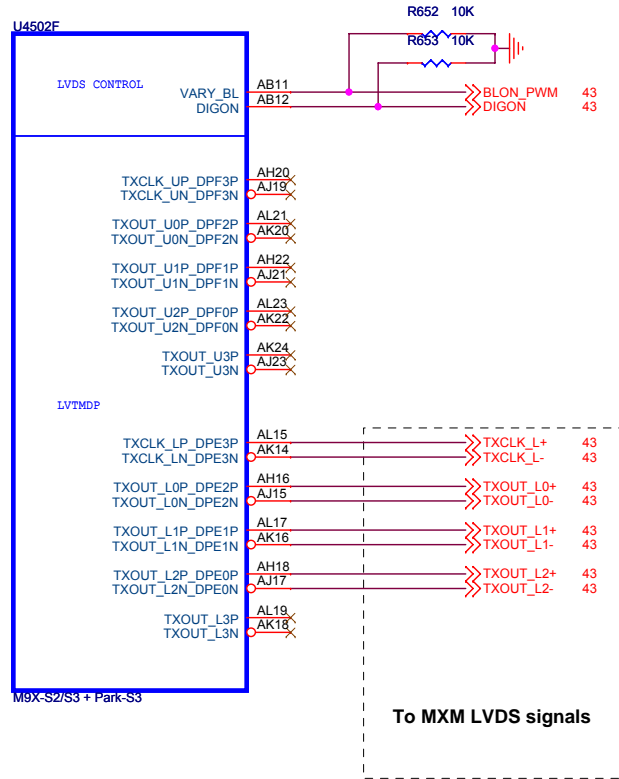


CONFIGURATION STRAPS			RECOMMENDED SETTINGS 0= DO NOT INSTALL RESISTOR 1= INSTALL 10K RESISTOR X= DESIGN DEPENDANT NA= NOT APPLICABLE
STRAPS	PIN	DESCRIPTION OF DEFAULT SETTINGS	
TX_PWRS_ENB	GPIO0	PCIe FULL TX OUTPUT SWING	X
TX_DEEMPH_EN	GPIO1	PCIe TRANSMITTER DE-EMPHASIS ENABLED	X
BIF_GEN2_EN_A	GPIO2	PCIe GEN2 ENABLED	X
RSVD	GPIO8	VGA ENABLED	0
BIF_VGA_DIS	GPIO9	RSVD	0
RSVD	GPIO21	RSVD	0
BIOS_ROM_EN	GPIO_22_ROMCSB	ENABLE EXTERNAL BIOS ROM	X
ROMIDCFG(2:0)	GPIO(13:11)	SERIAL ROM TYPE OR MEMORY APERTURE SIZE SELECT	X X X
VIP_DEVICE_STRAP_ENA	V2SYNC	IGNORE VIP DEVICE STRAPS	X
RSVD	GENERICC	RSVD	0
AUD[1]	HSYNC	AUD[1] AUD[0]	0
AUD[0]	VSYNC	0 0 No audio function 0 1 Audio for DisplayPort and HDMI if dongle is detected 1 0 Audio for DisplayPort only 1 1 Audio for both DisplayPort and HDMI	X X

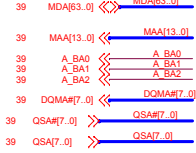
AMD RESERVED CONFIGURATION STRAPS	
H2SYNC	GENERICC
Provide pull-up pads for these straps - but do not populate. GPIOs functions on these signals must not conflict with the pin strap at Reset	
Provide pull-up pads for these straps - but do not populate. GPIOs functions on these signals must not conflict with the pin strap at Reset	
GPIO21_BB_EN	



LVDS Interface



BITLAND		Bitland Information Technology Co., Ltd. Notebook R&D Division	
Title Park-XT(DPEF_LVDS)			
Size B	Document Number BM5016		Rev 1.0
Date:	Thursday, August 05, 2010	Sheet	37 of 54



**MVDDQ = 1.5V FOR
DDR3 Memory**

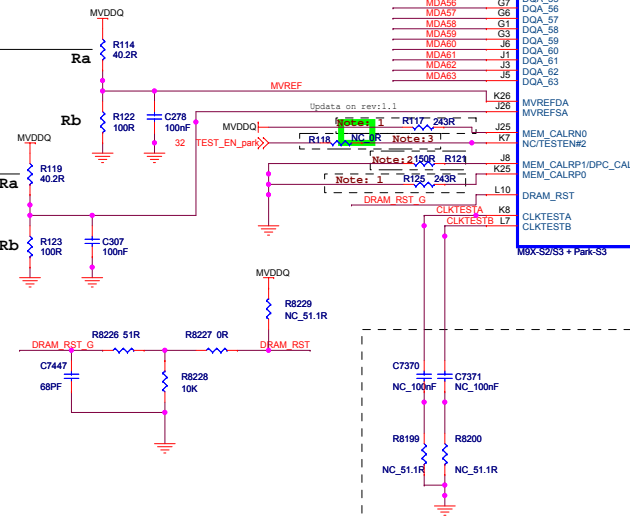
**PLACE MVREF DIVIDERS
AND CAPS CLOSE TO ASIC**

For M9X-S2/S3

DIVIDER RESISTORS	DDR2/DDR3	GDDR3
MVREF TO 1.8V (Ra)	100R	40.2R
MVREF TO GND (Rb)	100R	100R

For Park-S3

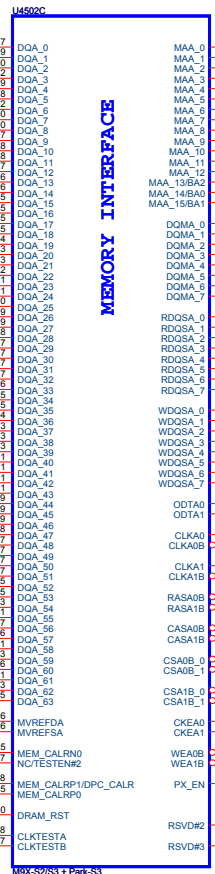
DIVIDER RESISTORS	DDR2/DDR3	GDDR3
MVREF TO 1.8V (Ra)	40.2R	40.2R
MVREF TO GND (Rb)	100R	100R



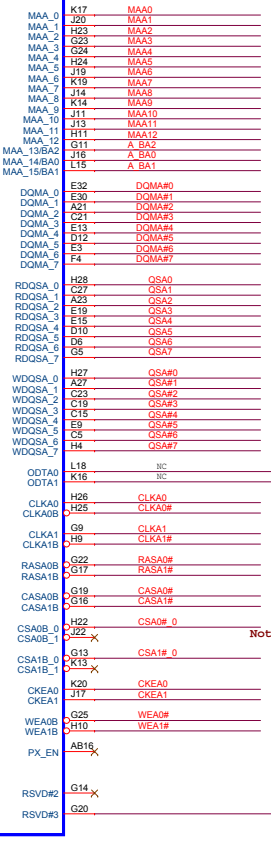
route 50ohms
single-ended/100ohms diff
and keep short

Use this option ONLY
for Park-S3

Differential for testing and
DUT component for normal operation.



**DDR3 Memory
Interface**

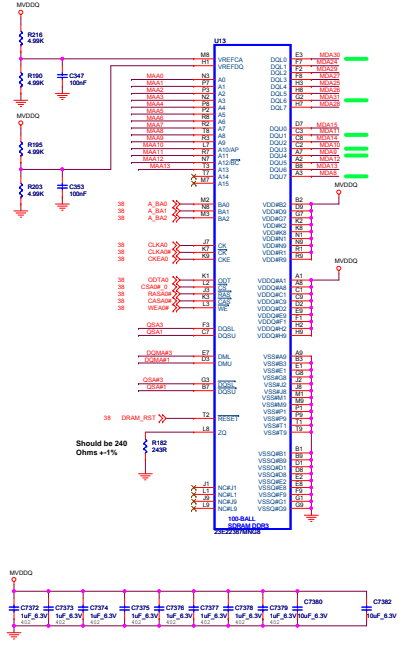
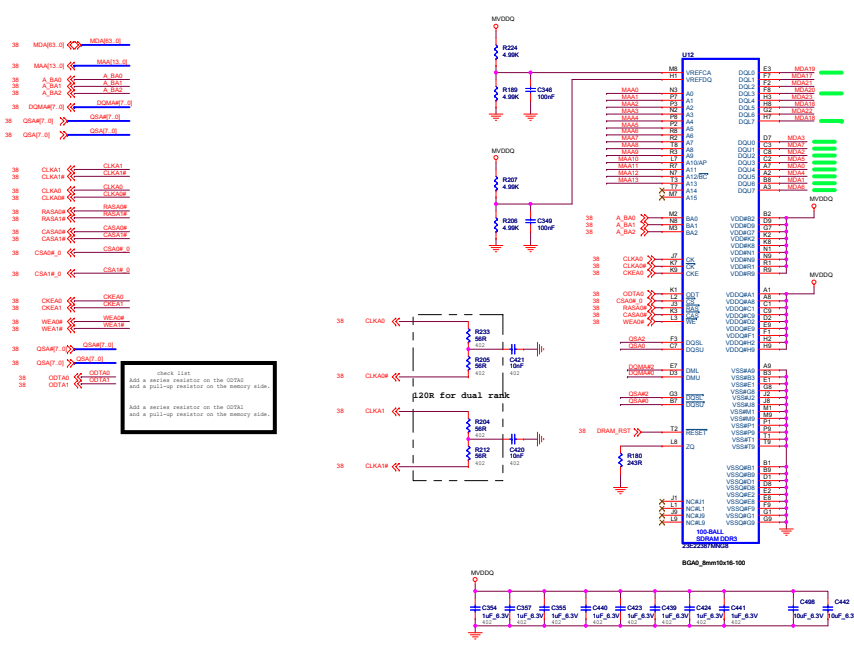


Note 1 : Do not Install for M9X-S2/S3, Install 240 Ohms 0.5% Resistor for PARK-S3.

Note 2 :For M9X-92/93, J8 Pin Connect to VSS through 240 Ohms(0.5%) resistor.
For Park-S3, J8 Pin Connect to VSS through 150 Ohms(1%) resistor for DPC_CALR

Note 3 :For M9X-92/93, K7 Pin (NC_MEM_CALRP1) is Not connected.
For PARK-S3, K7 Pin (TESTEN#2) connect to TEST_EN Signal at AP24

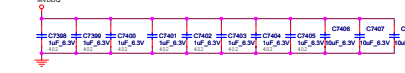
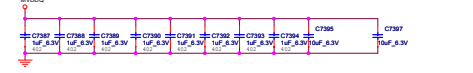
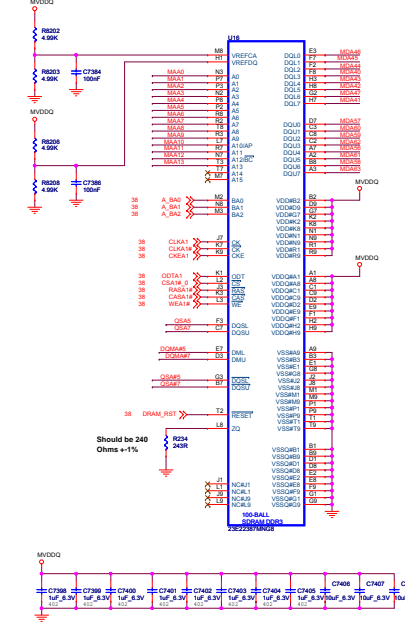
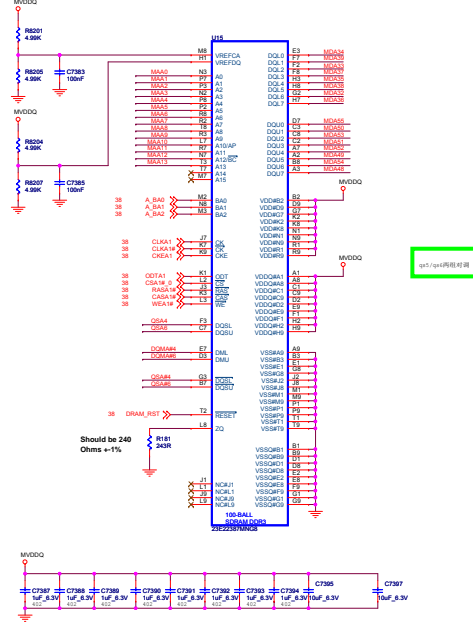




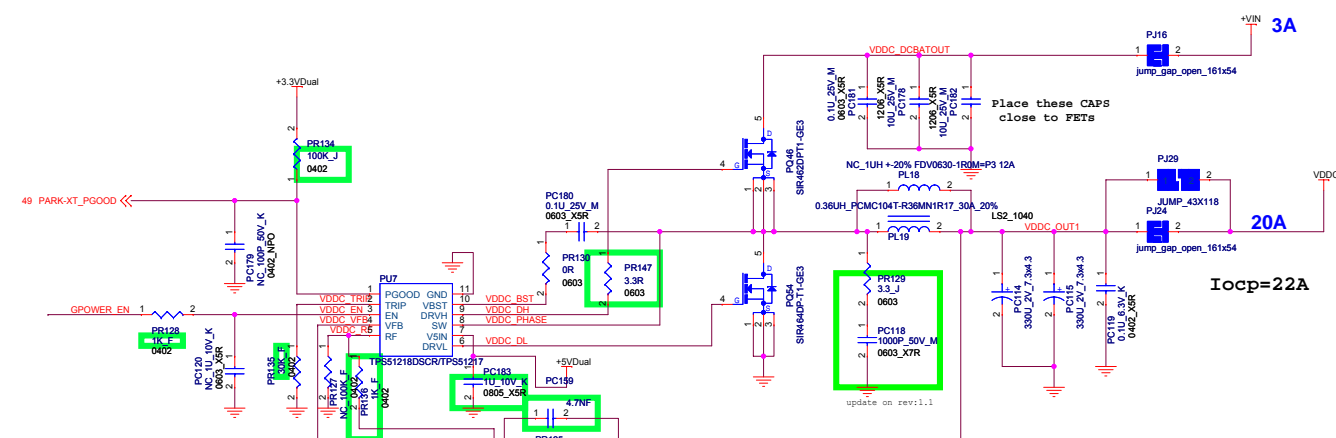
For PARK-S3 with DDR3: Support MAA13-MAA0 Address or 128KX16 DDR3.

RANK1: 256MB/ 512MB DDR3

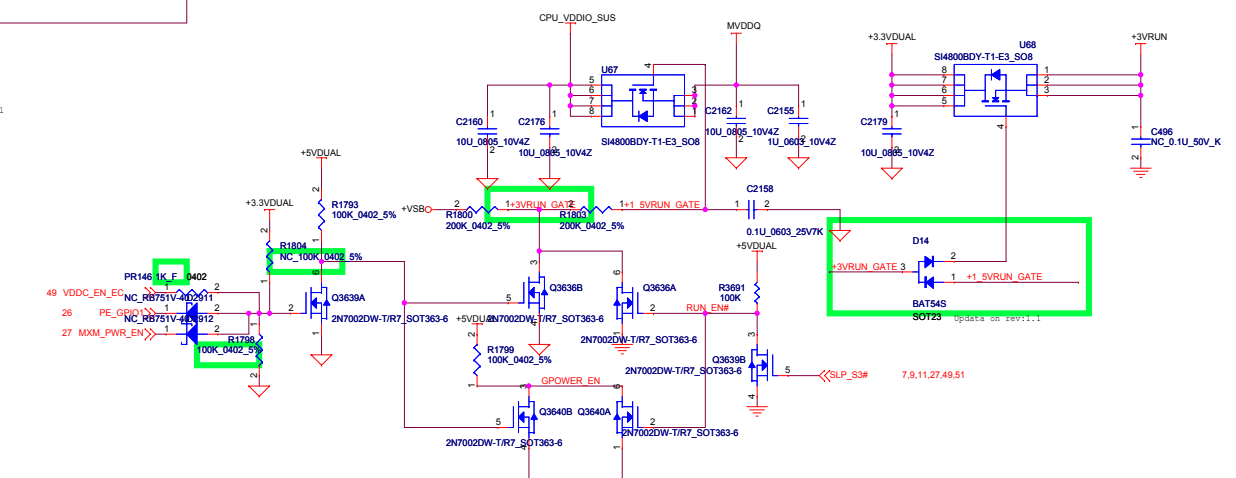
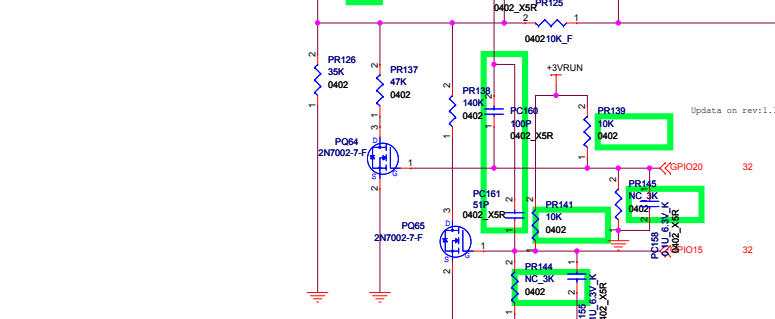
PARK_XT ENG=750MHZ ,Mem=900MHZ DDR3



COMPONENTS SHOWN ARE EXAMPLES ONLY, AND NOT NECESSARILY QUALIFIED FOR PMX-S3/S WITH DDR3. Support MAA2-MAA0 Address or 64KX16 DDR3. MAA13 is NC

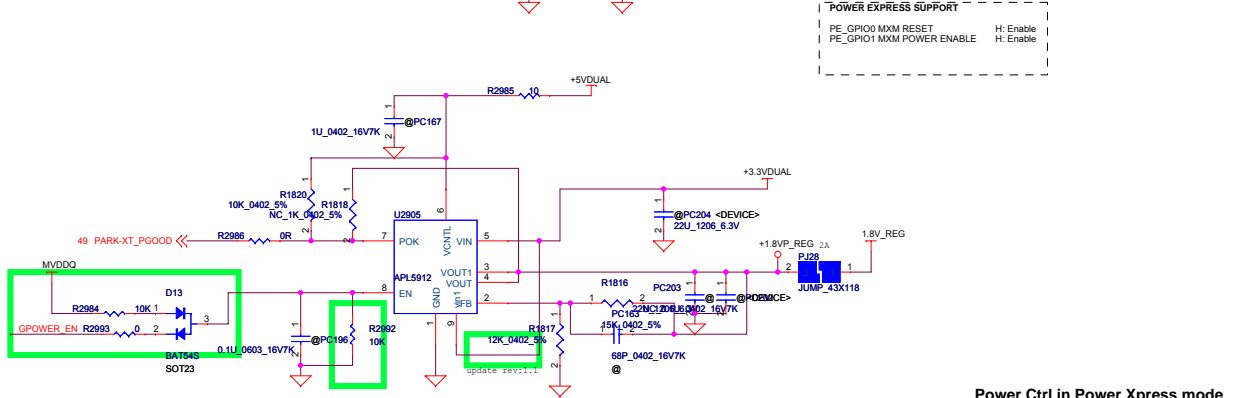
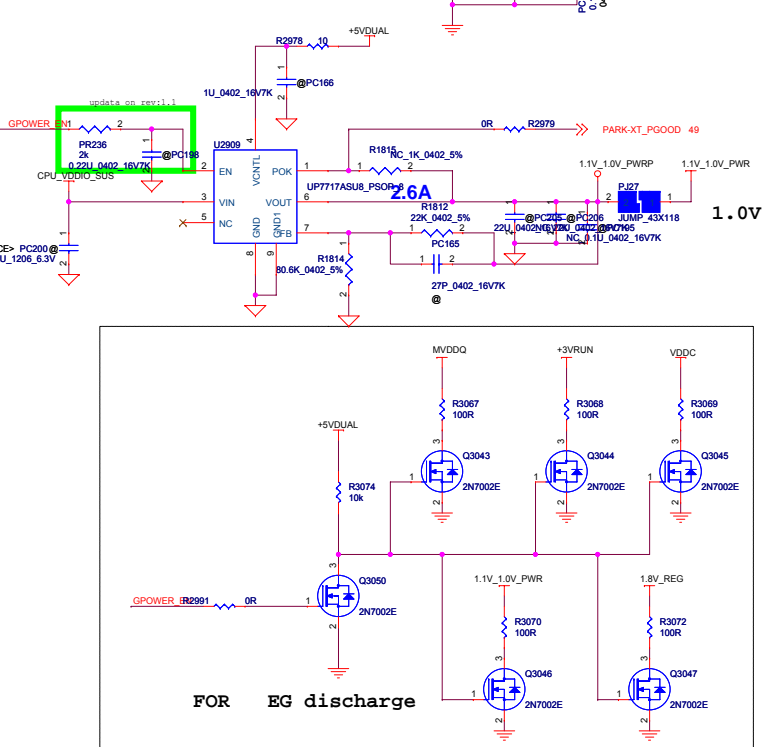


GPIO20 (p8)	GPIO15 (n1)	vddc	R top	R bot
0	0	0.9V	10Kohm	35Kohm
0	1	0.95V	10Kohm	35K//140K=28 KOhm
x	x	x	x	x
1	1	1.12V	10Kohm	35K//47K//140K=17.5 KOhm



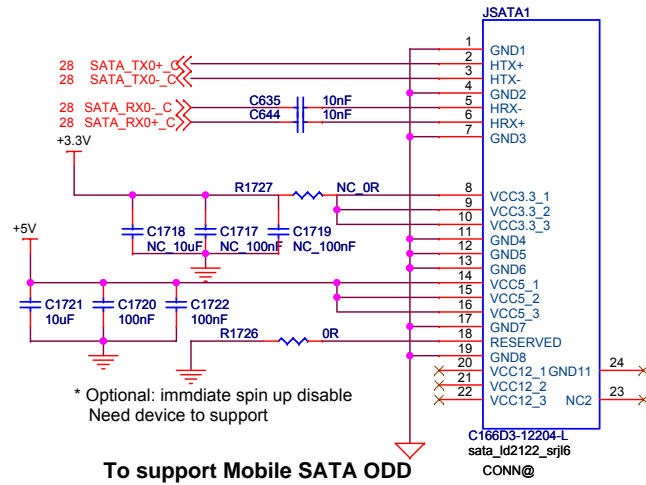
POWER EXPRESS SUPPORT

- PE_GPIO1 MXM RESET H: Enable
- PE_GPIO1 MXM POWER ENABLE H: Enable

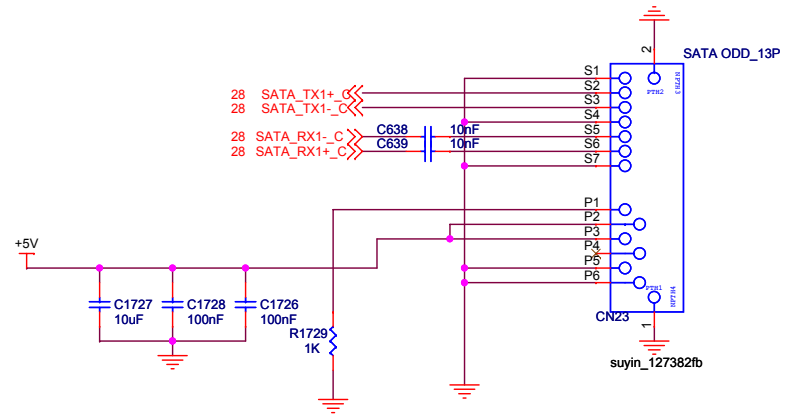


Power Ctrl in Power Xpress mode

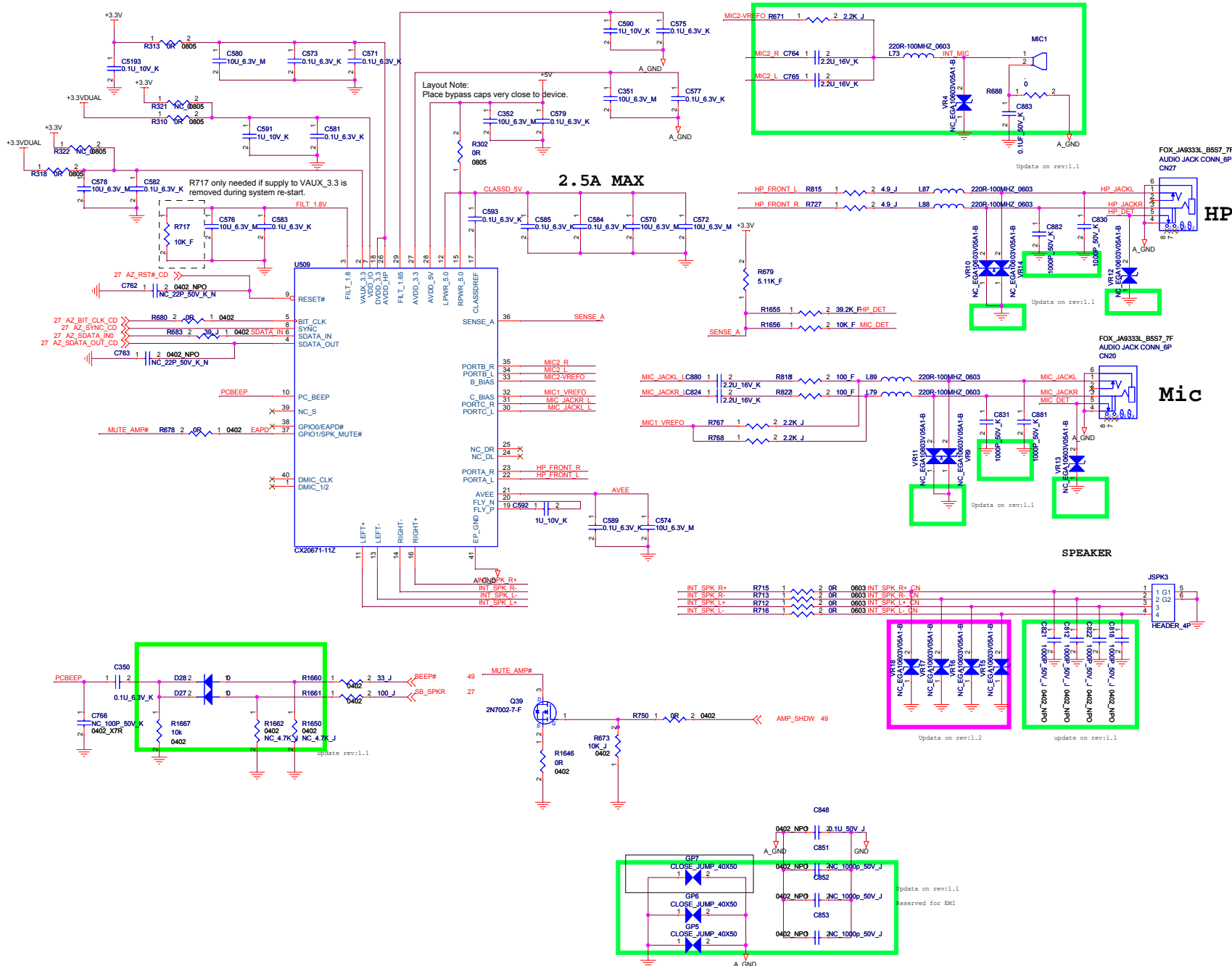
SATA HDD Conn.

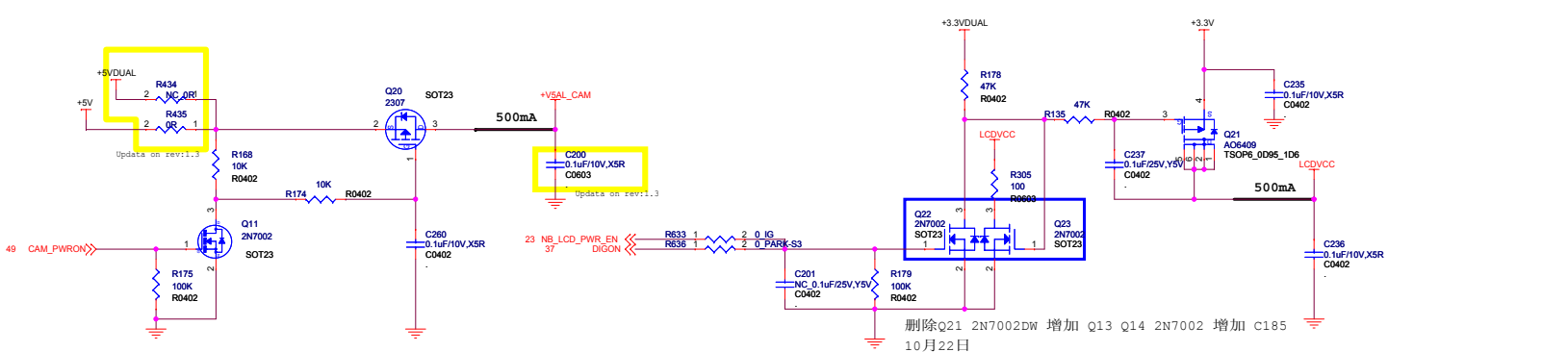
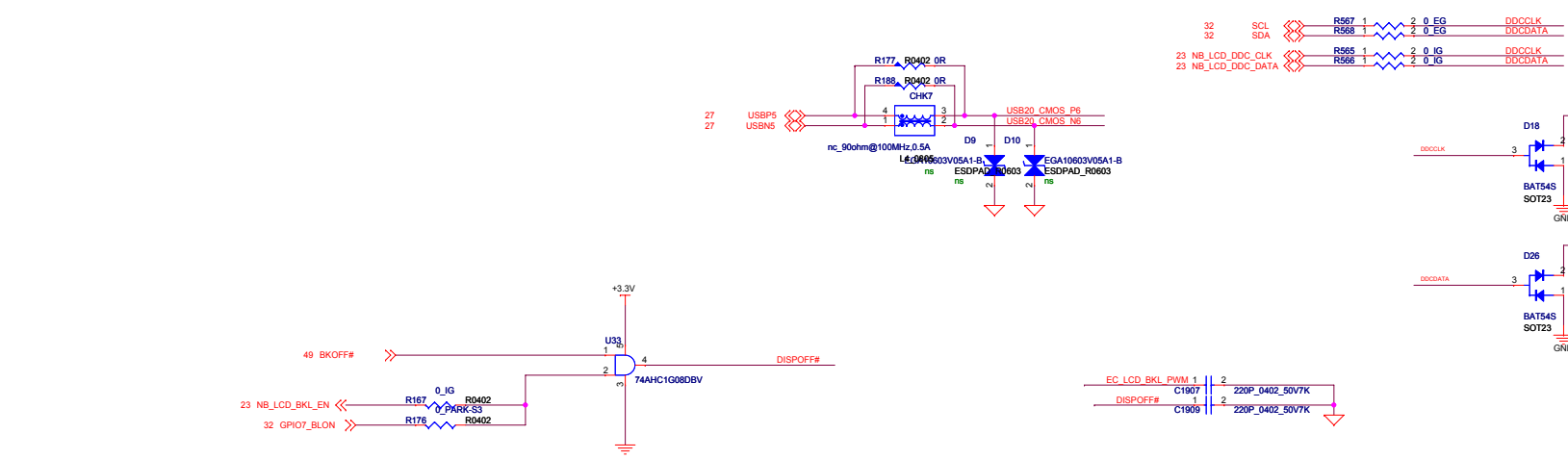
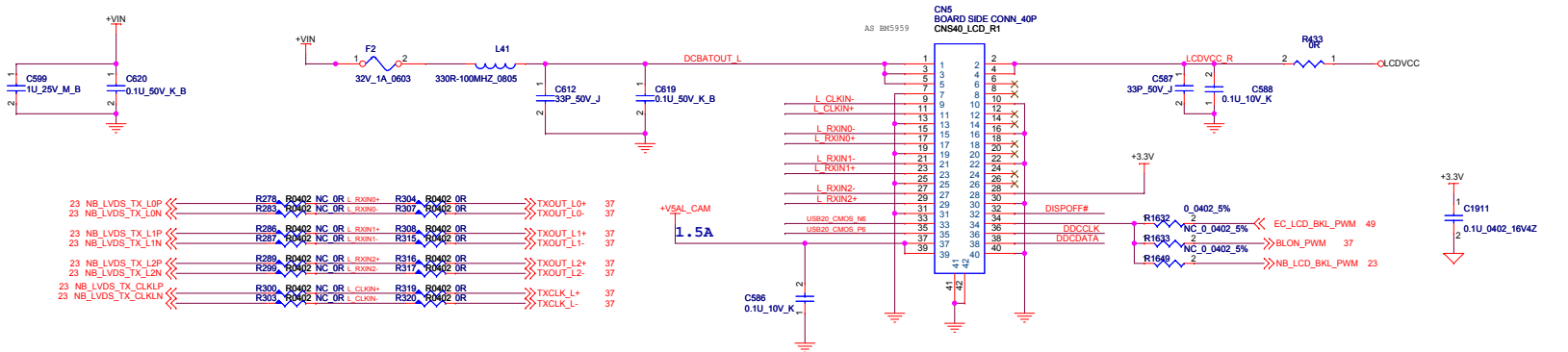


To support Mobile SATA ODD through cable



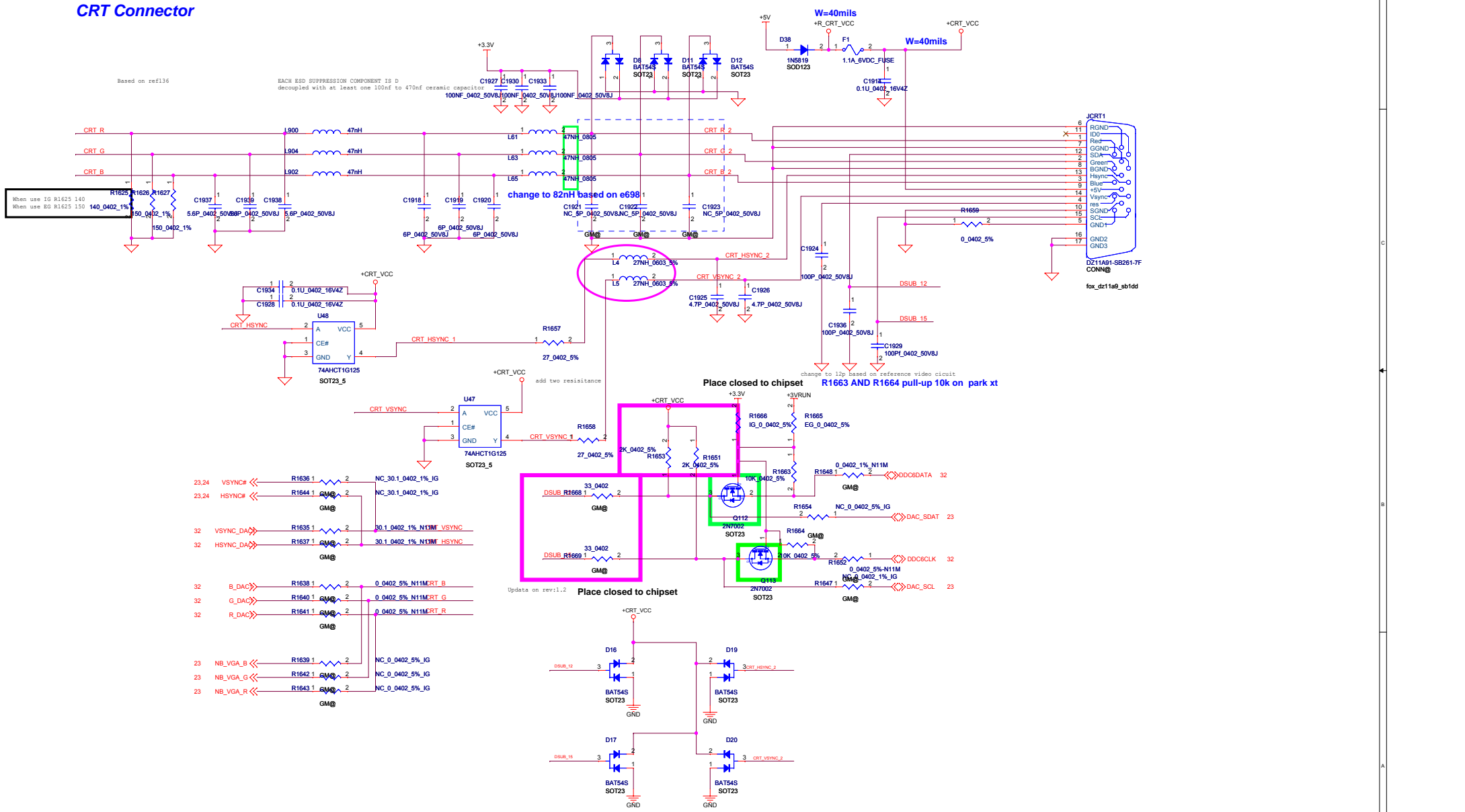
BITLAND		Bitland Information Technology Co., Ltd.	
		Notebook R&D Division	
Title SATA HDD /ODD			
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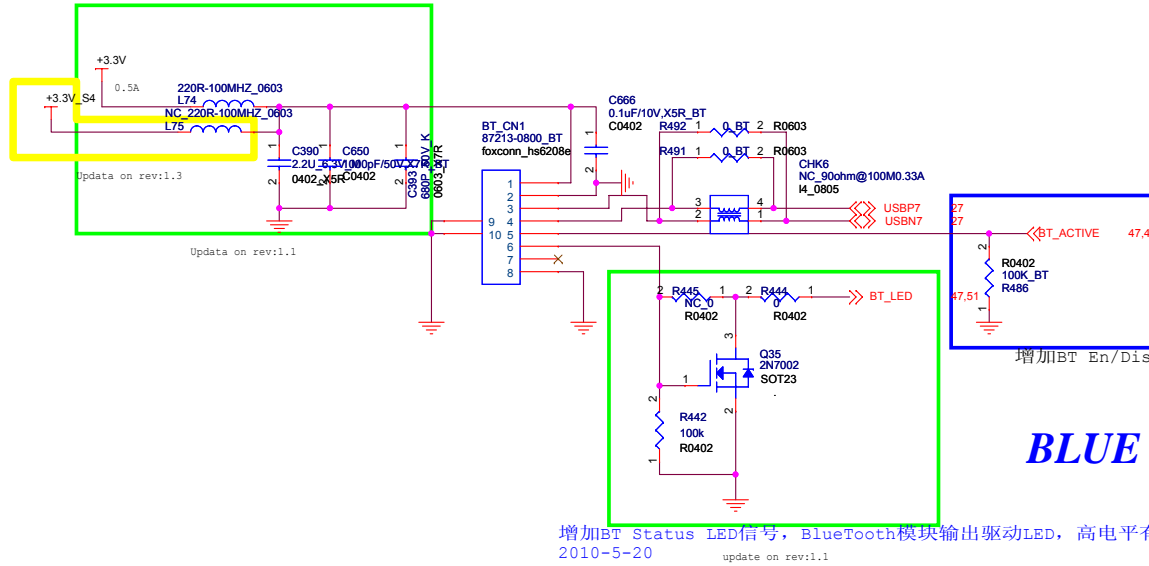




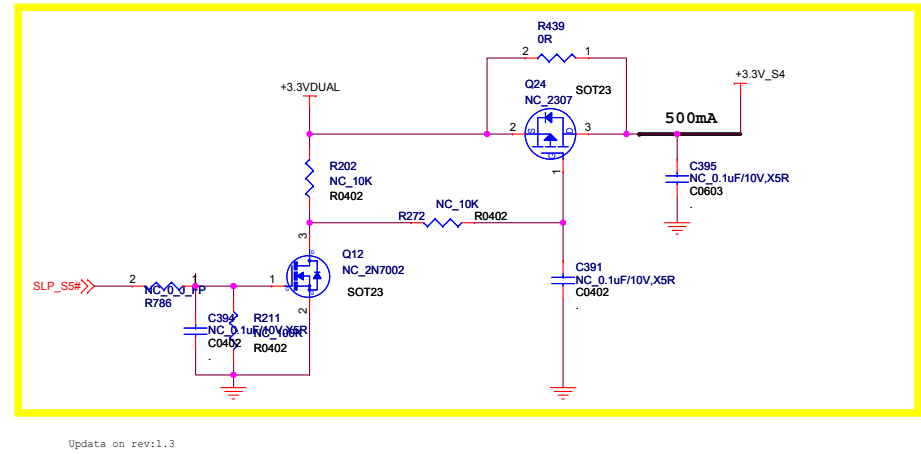
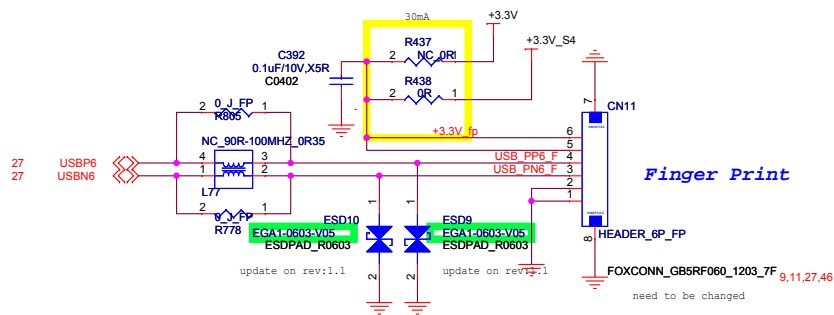
删除Q21 2N7002DW 增加 Q13 Q14 2N7002 增加 C185
10月22日

CRT Connector

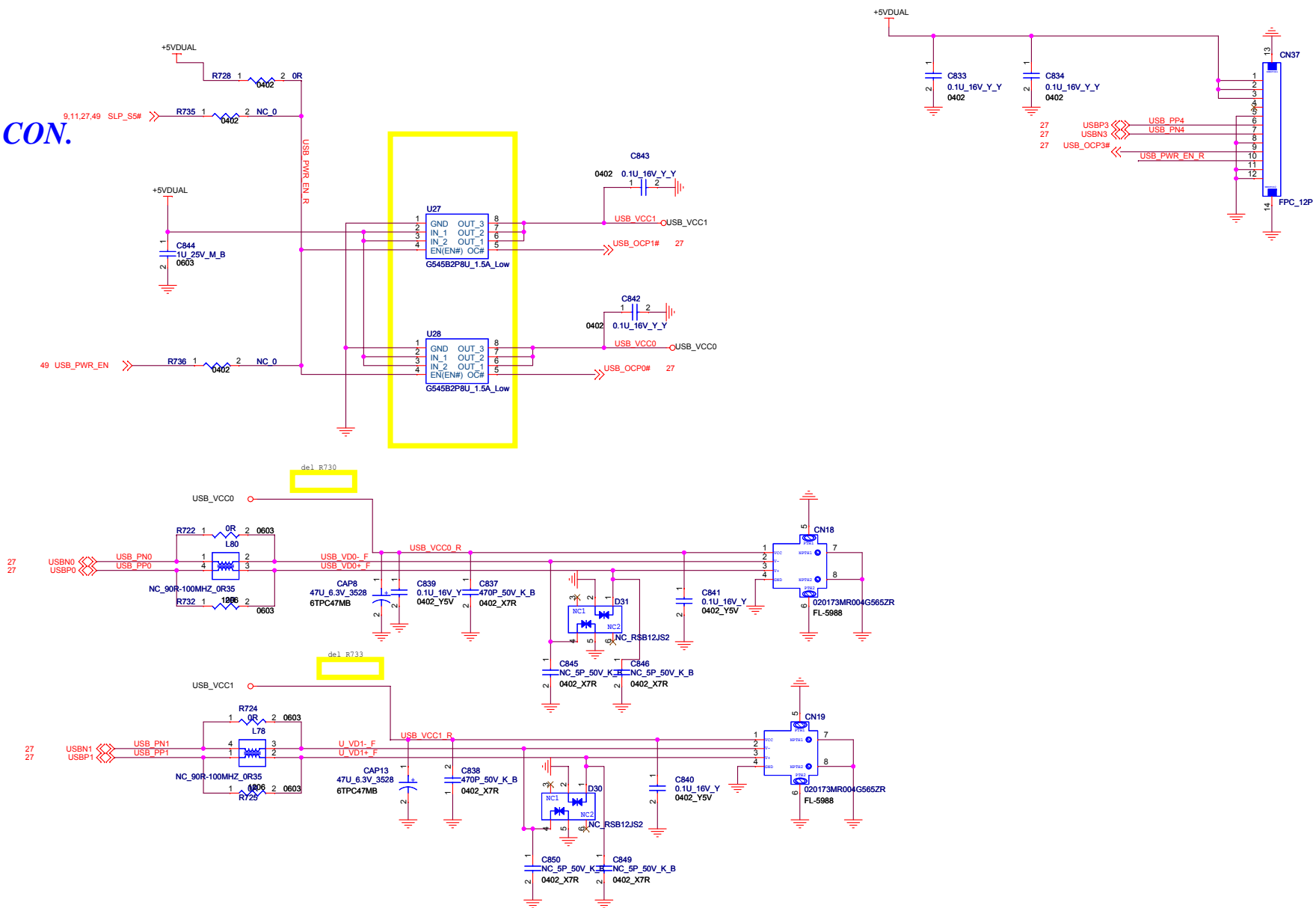


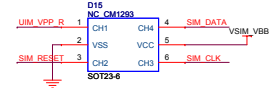
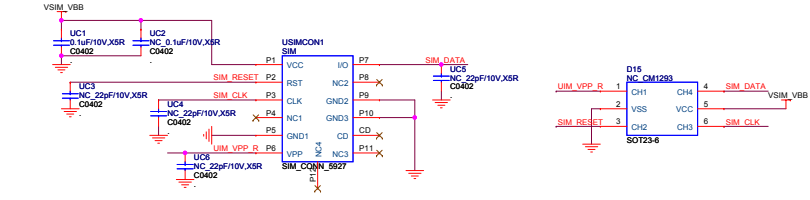
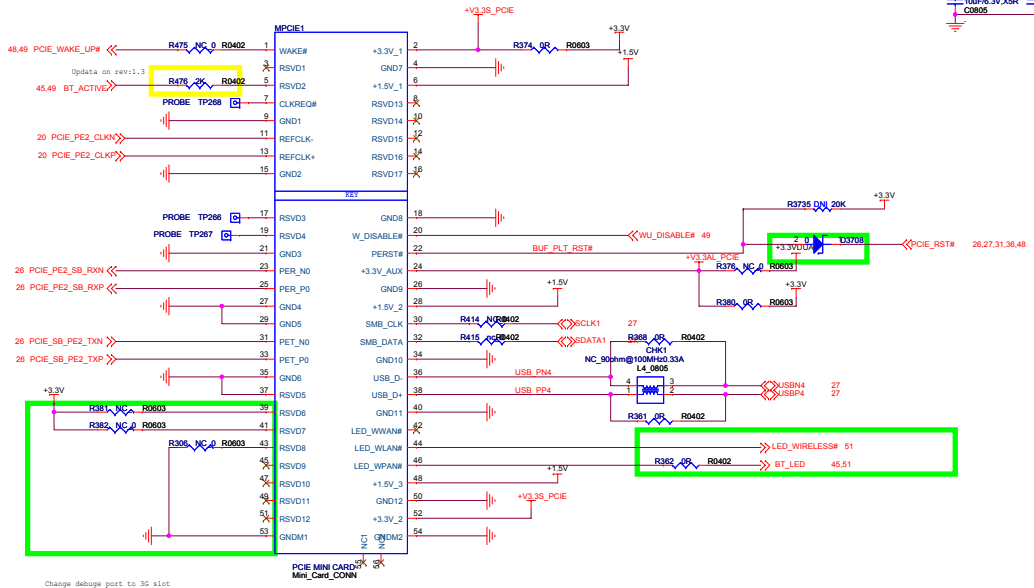
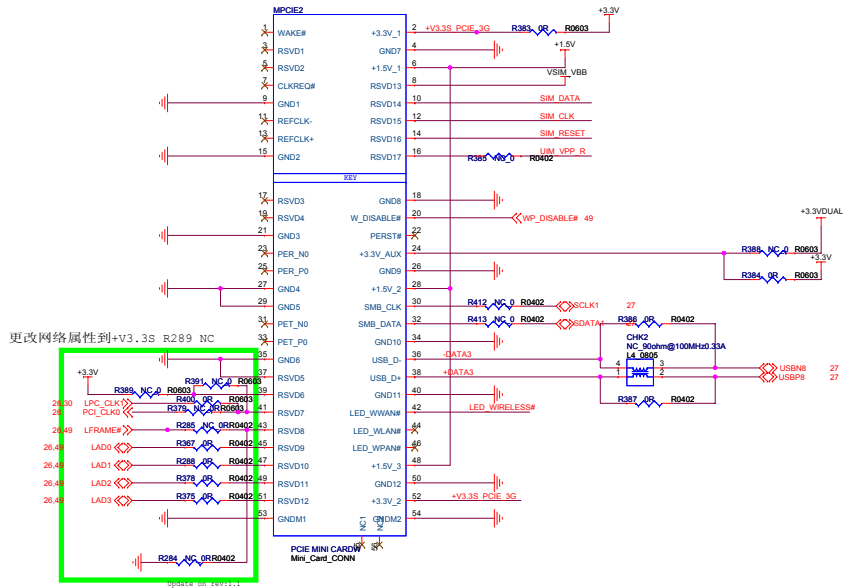
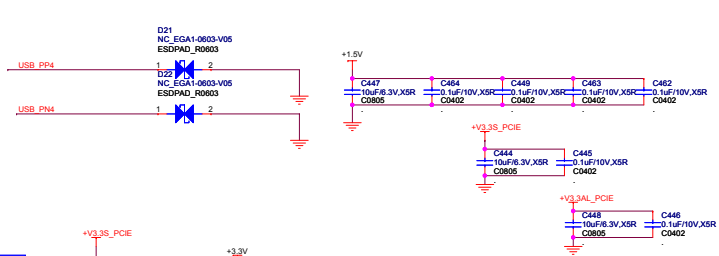
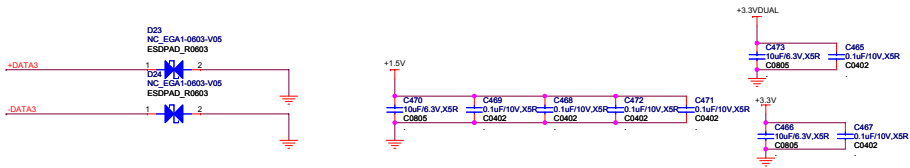


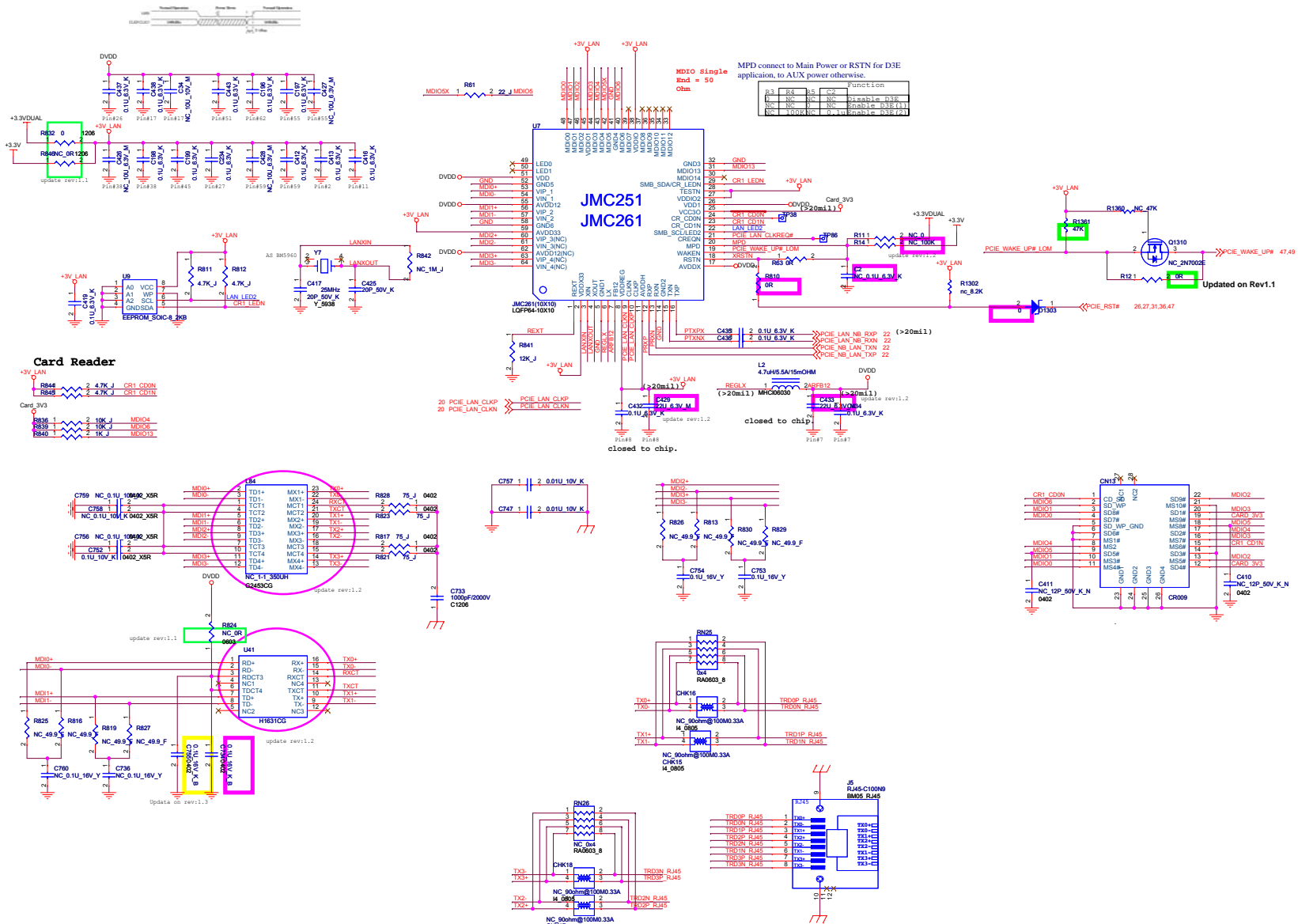
BLUE TOOTH



USB CON.



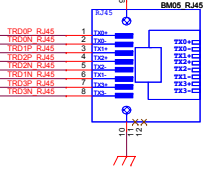
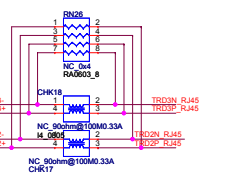
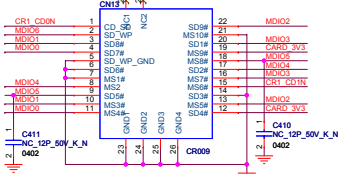
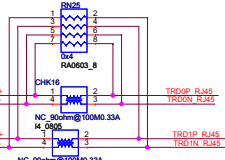
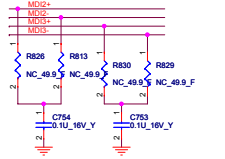
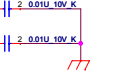
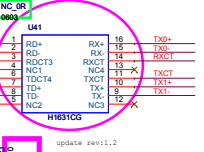
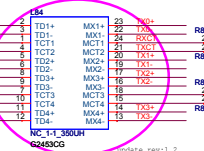


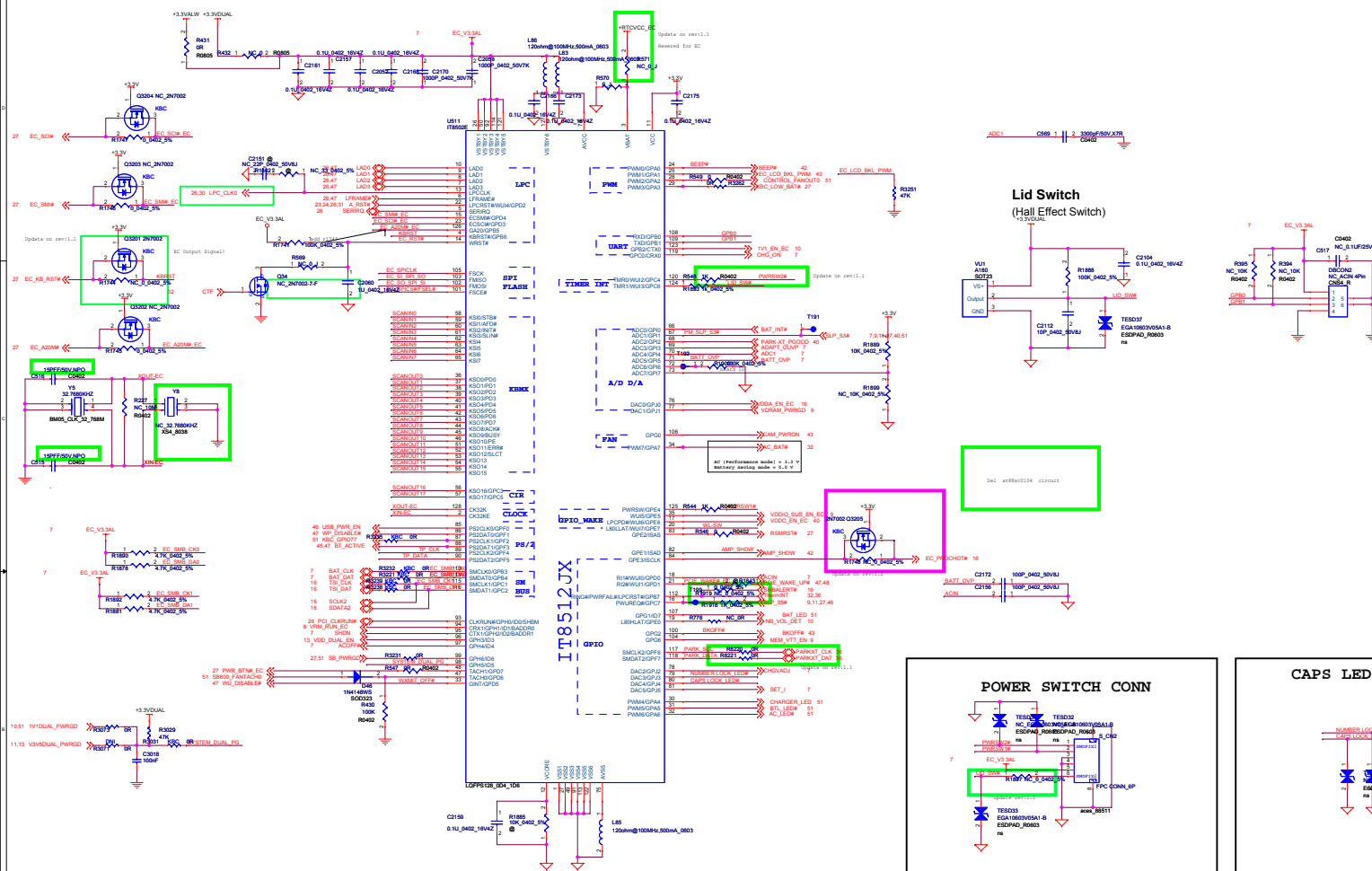


MDIO connect to Main Power or RSTN for D3E application, to AUX power otherwise.

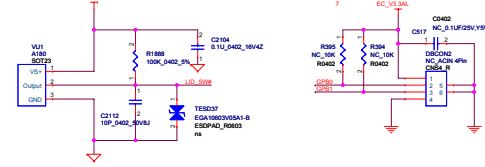
R3	R4	R5	R2	Function
NC	NC	NC	NC	Disable D3E
NC	NC	NC	NC	Disable D3E11
NC	NC	NC	NC	Disable D3E12

Card Reader



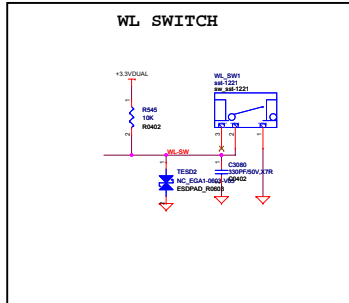
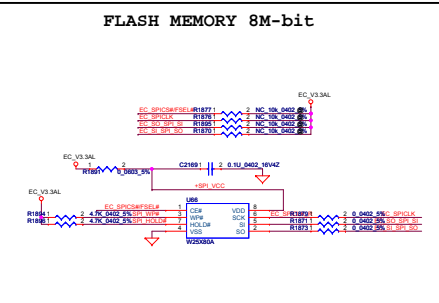
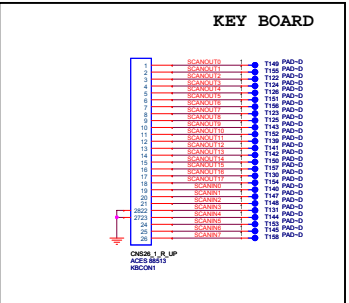
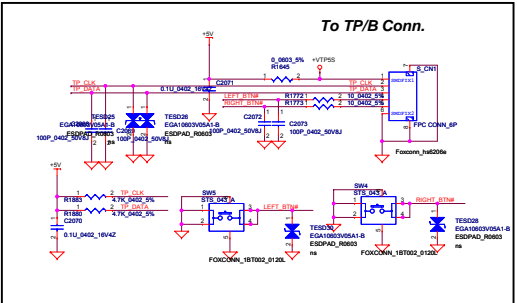
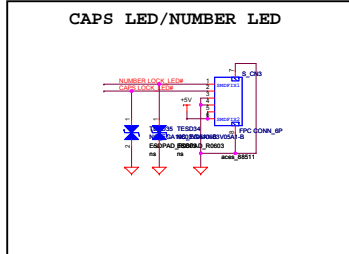
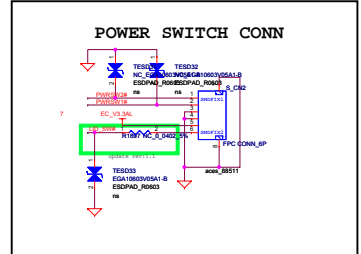


Lid Switch (Hall Effect Switch)



DUAL RAILS ENABLE

DUAL rails can be configured to be on at all times
 DUAL rails can also be configured to conserve power during S5 when operating from battery
 In this case DUAL rails can be configured to turn on only in response to a power button press
 the keyboard controller typically will control this function significantly reducing hardware



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D

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C

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B

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A

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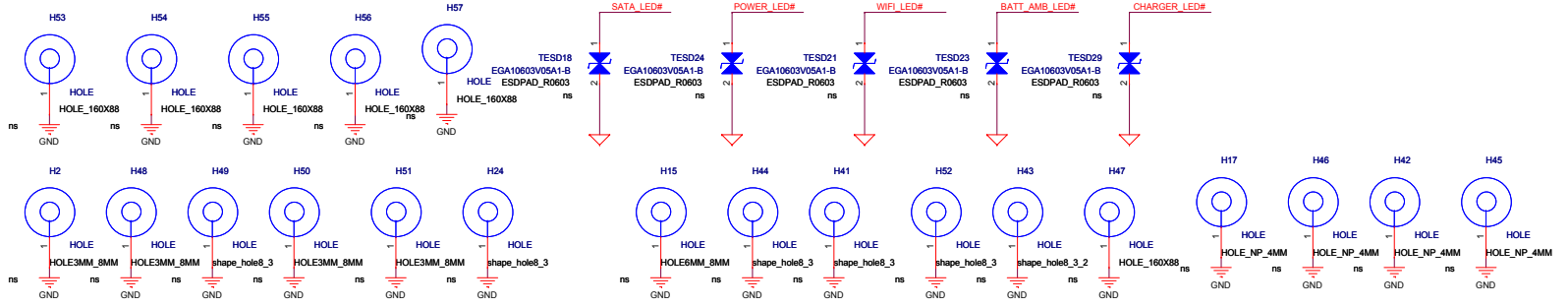
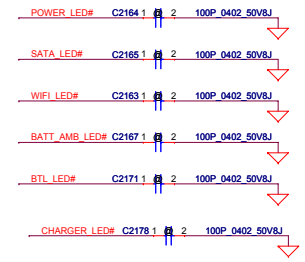
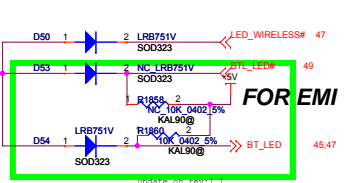
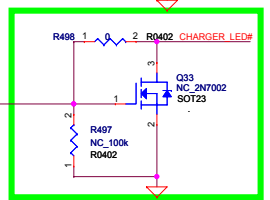
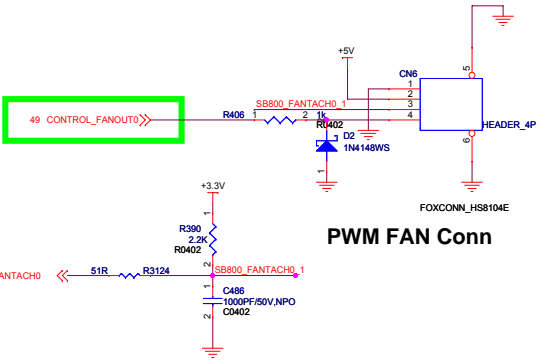
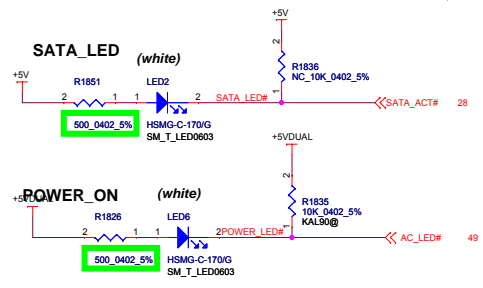
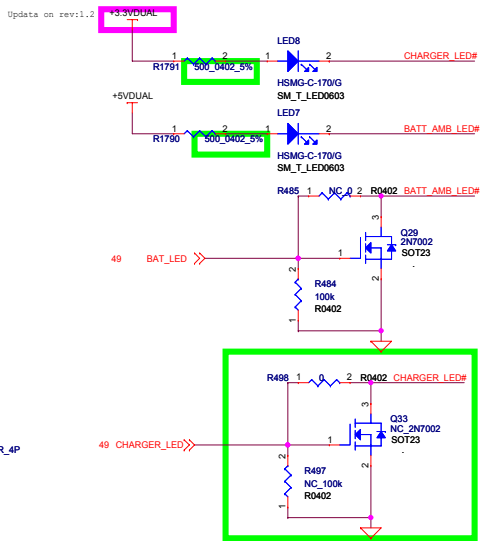
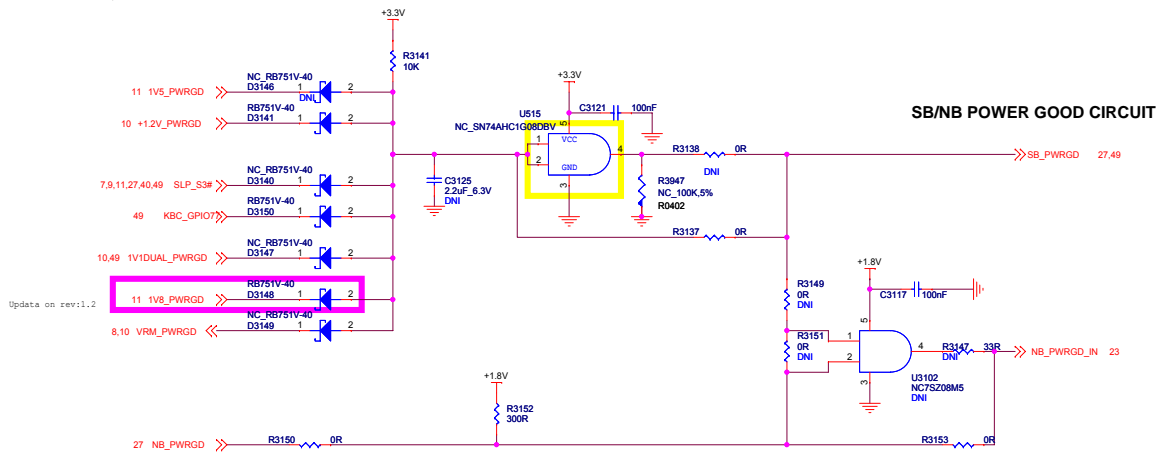
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Title change history			
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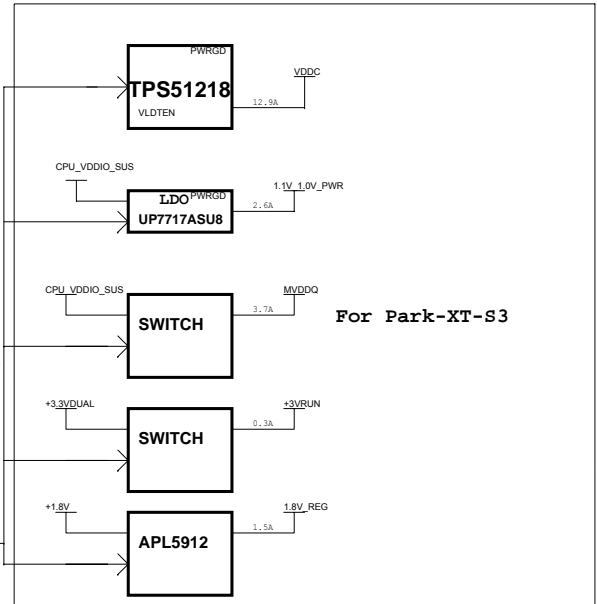
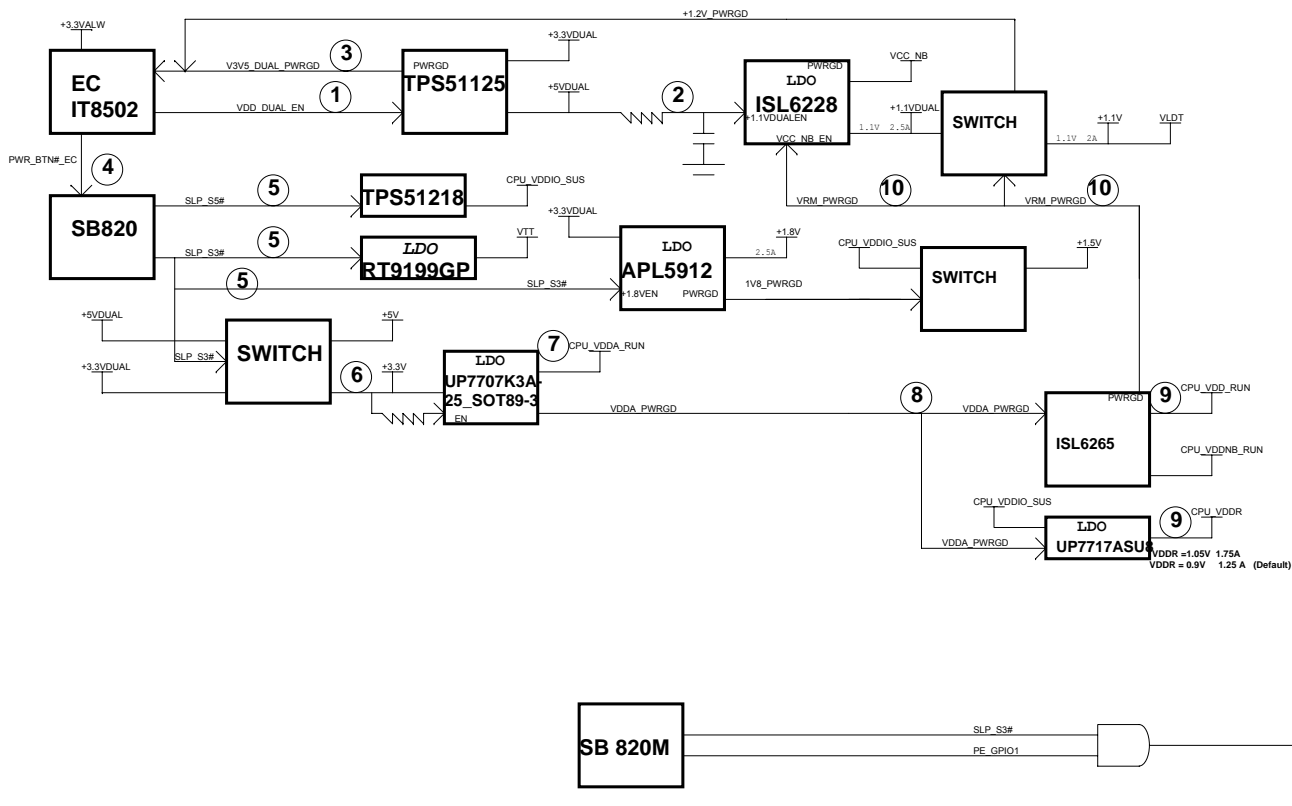
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Power on Sequence required:

SB800:

- 1, +3.3VDUAL ramp before +1.1VDUAL
- 2, +3.3V ramp before +1.8v
- 3, +1.8V ramp before +1.1v
- 4, +3.3v ramp before +1.1v
- 5, +3.3VALW_R ramping down time > 300us
- 6, 50uS <= All power rails except +3.3VALW_R <= 40mS
- 7, 100uS <= +3.3VALW_R <= 40mS

RS880:

- 1, 0 < (+3.3V) - (+1.8v) < 2.1
- 2, +1.8V ramp before +1.1v
3. +1.1V ramp before VCC_NB

各电源PWM/L/MOS选型

POWER	PWM	L	H_GATE	L_GATE
+3.3VDUAL (+3.3V 8A)	TI/TPS51125RGER	HB90479MA0LFE 4.7uH±20% 5.5A 40mD SMD-E.86x6.47x3.0mm	30V 11.6A RDS(ON)<22mΩ(VDS=4.5V)	AC4468
+5VDUAL (+5V 8A)	VQFN24	HB90479MA0LFE 4.7uH±20% 5.5A 40mD SMD-E.86x6.47x3.0mm	30V 11.6A RDS(ON)<22mΩ(VDS=4.5V)	AC4468
VCC_NB (+1.1V 12A)	ISL6228HRTZ-T	HB90109M00LFE 1.0H ±20% 12A 10mD SMD-E.86x7.3x3.0mm	VISHAY/SI4172DY-T1-GE3 2.0A 17.20V 1.06mΩ(1.5V) 20-39pin	VISHAY/SI4168DY-T1-GE3 2.0A 17.20V 1.06mΩ(1.5V) 20-39pin
VLDI (+1.2V 4A)	TOFN28	HB90479MA0LFE 4.7uH±20% 5.5A 40mD SMD-E.86x6.47x3.0mm	L/H integrated (待定)	
VDDIO_SUS (+1.3V 31A)	TPS51218 DQC	HB90109M00LFE 1.0H ±20% 12A 10mD SMD-E.86x7.3x3.0mm	VISHAY/SI4172DY-T1-GE3 2.0A 17.20V 1.06mΩ(1.5V) 20-39pin	VISHAY/SI4168DY-T1-GE3 2.0A 17.20V 1.06mΩ(1.5V) 20-39pin
CPU_VDD_RUN (+1.375~+1.3V 36A)	ISL6265 QFN48	HB90479MA0LFE 4.7uH±20% 5.5A 40mD SMD-E.86x6.47x3.0mm	PHASE1 VISHAY/SIR462DP-T1-GE3 2.0A 17.20V 1.06mΩ(1.5V) 20-39pin	MISHAY/SI466DY-T1-E3/GE3(two) 2.0A 17.20V 1.06mΩ(1.5V) 20-39pin
CPU_VDDNB_RUN (+1.3V 4A)		HB90479MA0LFE 4.7uH±20% 5.5A 40mD SMD-E.86x6.47x3.0mm	PHASE2 VISHAY/SIR462DP-T1-GE3 2.0A 17.20V 1.06mΩ(1.5V) 20-39pin	MISHAY/SI466DY-T1-E3/GE3(two) 2.0A 17.20V 1.06mΩ(1.5V) 20-39pin
CPU_VDDNB_RUN (+1.3V 4A)	ISL6251HAZ SSOP24_25_150	HB90100MA0LFE 10uH±20% ICC=4A,DCR=Max 71.2mΩ SMD-E.86x6.47x3.0mm	AOS/AON7408 2.0A RDS(ON)<3.6mΩ(VDS=4.5V) 20-39pin	AOS/AON7702 2.0A RDS(ON)<3.6mΩ(VDS=4.5V) 20-39pin

LDO

VTT	RT9199GP	(+1.5V~+0.75 1.5A)
CPU_VDDA_RUN	APL5508_25DC_TRL_S0789_3	(+3.3V~+2.9V 5000A)
+1.8V	APL5930	(+3.3V~+1.8 1.5A)
CPU_VDDR	APL5912	(+1.5V~+1.05V 4A)
+1.1VDUAL	APL5930	(+3.3V~+1.1V 5000A)

SWITCH

INPUT(V)	OUTPUT(V)	MOB
+5VDUAL	+5V	AO4468 (8A)
+3.3VDUAL	+3.3V	AO4468 (8A)
VLDI	+1.1V	JUNKER (4A)
CPU_VDDIO_SUS	+1.5V	AO4468 (5A)